

# LUH23-LD

# Hardware Design

**LTE Standard Series**

Version: 0.1

Date: 2025-01-23

Status: Draft

**Our aim is to provide timely and comprehensive services to our customers. If you require any assistance, please contact our headquarters:**

**NetPrisma US INC.**

100 N HOWARD ST STE R, SPOKANE, WA, 99201

Email: [Info@netprisma.us](mailto:Info@netprisma.us)

**Or our local offices. For more information, please visit:**

<https://www.netprisma.us/sales-support/>.

**For technical support, or to report documentation errors, please visit:**

<https://www.netprisma.us/tech-support/>.

Or email us at: [support@netprisma.us](mailto:support@netprisma.us).

## Legal Notices

We offer information as a service to you. The provided information is based on your requirements and we make every effort to ensure its quality. You agree that you are responsible for using independent analysis and evaluation in designing intended products, and we provide reference designs for illustrative purposes only. Before using any hardware, software or service guided by this document, please read this notice carefully. Even though we employ commercially reasonable efforts to provide the best possible experience, you hereby acknowledge and agree that this document and related services hereunder are provided to you on an “as available” basis. We may revise or restate this document from time to time at our sole discretion without any prior notice to you.

## Use and Disclosure Restrictions

### License Agreements

Documents and information provided by us shall be kept confidential, unless specific permission is granted. They shall not be accessed or used for any purpose except as expressly provided herein.

### Copyright

Our and third-party products hereunder may contain copyrighted material. Such copyrighted material shall not be copied, reproduced, distributed, merged, published, translated, or modified without prior written consent. We and the third party have exclusive rights over copyrighted material. No license shall be granted or conveyed under any patents, copyrights, trademarks, or service mark rights. To avoid ambiguities, purchasing in any form cannot be deemed as granting a license other than the normal non-exclusive, royalty-free license to use the material. We reserve the right to take legal action for noncompliance with abovementioned requirements, unauthorized use, or other illegal or malicious use of the material.

### Trademarks

Except as otherwise set forth herein, nothing in this document shall be construed as conferring any rights to use any trademark, trade name or name, abbreviation, or counterfeit product thereof owned by NetPrisma or any third party in advertising, publicity, or other aspects.

### Third-Party Rights

This document may refer to hardware, software and/or documentation owned by one or more third parties (“third-party materials”). Use of such third-party materials shall be governed by all restrictions and obligations applicable thereto.

We make no warranty or representation, either express or implied, regarding the third-party materials, including but not limited to any implied or statutory, warranties of merchantability or fitness for a particular purpose, quiet enjoyment, system integration, information accuracy, and non-infringement of any third-party intellectual property rights with regard to the licensed technology or use thereof. Nothing herein constitutes a representation or warranty by us to either develop, enhance, modify, distribute, market, sell, offer for sale, or otherwise maintain production of any our products or any other hardware, software, device, tool, information, or product. We moreover disclaim any and all warranties arising from the course of dealing or usage of trade.

## Privacy Policy

To implement module functionality, certain device data are uploaded to NetPrisma’s or third-party’s servers, including carriers, chipset suppliers or customer-designated servers. NetPrisma, strictly abiding by the relevant laws and regulations, shall retain, use, disclose or otherwise process relevant data for the

purpose of performing the service only or as permitted by applicable laws. Before data interaction with third parties, please be informed of their privacy and data security policy.

## Disclaimer

- a) We acknowledge no liability for any injury or damage arising from the reliance upon the information.
- b) We shall bear no liability resulting from any inaccuracies or omissions, or from the use of the information contained herein.
- c) While we have made every effort to ensure that the functions and features under development are free from errors, it is possible that they could contain errors, inaccuracies, and omissions. Unless otherwise provided by valid agreement, we make no warranties of any kind, either implied or express, and exclude all liability for any loss or damage suffered in connection with the use of features and functions under development, to the maximum extent permitted by law, regardless of whether such loss or damage may have been foreseeable.
- d) We are not responsible for the accessibility, safety, accuracy, availability, legality, or completeness of information, advertising, commercial offers, products, services, and materials on third-party websites and third-party resources.

**Copyright © NetPrisma US 2024. All rights reserved.**

# Revision History

Version	Date	Description
-	2025-01-23	Creation of the document

# Contents

Revision History .....	3
Contents .....	4
Table Index .....	6
Figure Index .....	7
<b>1 Introduction .....</b>	<b>8</b>
<b>2 Product Overview.....</b>	<b>9</b>
2.1. Frequency Bands and Functions .....	9
2.2. Key Features .....	9
2.3. EVB Kit .....	11
<b>3 Application Interfaces .....</b>	<b>12</b>
3.1. General Description .....	12
3.2. Pin Assignment .....	12
3.3. Pin Description .....	13
3.4. Operating Modes.....	18
3.5. Power Saving .....	19
3.5.1. Sleep Mode .....	19
3.5.1.1. UART Application Scenario .....	19
3.5.1.2. USB Application with USB Remote Wakeup Function .....	20
3.5.1.3. USB Application with USB Suspend/Resume and RI Function.....	20
3.5.1.4. USB Application without USB Suspend Function .....	21
3.5.2. Airplane Mode .....	22
3.6. Power Supply .....	22
3.6.1. Power Supply Pins .....	22
3.6.2. Voltage Stability Requirements .....	22
3.6.3. Reference Design for Power Supply .....	23
3.6.4. Power Supply Voltage Monitoring.....	24
3.7. Turn On .....	24
3.7.1. Turn On with PWRKEY .....	24
3.8. Turn Off .....	25
3.8.1. Turn Off with PWRKEY .....	26
3.8.2. Turn Off with AT Command .....	26
3.9. Reset .....	26
3.10. (U)SIM Interfaces .....	28
3.11. USB Interface .....	30
3.12. UART Interfaces.....	31
3.13. PCM and I2C Interfaces.....	32
3.14. SPI Interface .....	34
3.15. Indication Signals .....	35
3.15.1. Network Status Indication .....	35
3.15.2. STATUS .....	36
3.15.3. RI .....	36
3.16. ADC Interface.....	37
3.17. USB_BOOT Interface.....	38
<b>4 RF Specifications .....</b>	<b>40</b>
4.1. Cellular Network.....	40
4.1.1. Antenna Interfaces & Frequency Bands .....	40
4.1.2. Tx Power .....	41
4.1.3. Rx Sensitivity .....	41
4.1.4. Reference Design .....	41
4.2. GNSS (Optional) .....	42
4.2.1. Antenna Interfaces & Frequency Bands .....	42
4.2.2. GNSS Performance .....	43
4.2.3. Reference Design .....	44
4.2.4. Layout Guidelines .....	44
4.3. RF Routing Guidelines .....	45
4.4. Antenna Design Requirements .....	46
4.5. RF Connector Recommendation .....	47
<b>5 Electrical Characteristics and Reliability .....</b>	<b>49</b>

5.1.	Absolute Maximum Ratings .....	49
5.2.	Power Supply Ratings.....	49
5.3.	Operating and Storage Temperatures .....	49
5.4.	Power Consumption.....	50
5.5.	GNSS Power Consumption .....	51
5.6.	ESD Protection.....	51
5.7.	Thermal Dissipation .....	52
<b>6</b>	<b>Mechanical Information.....</b>	<b>54</b>
6.1.	Mechanical Dimensions .....	54
6.2.	Recommended Footprint .....	55
6.3.	Top and Bottom Views.....	56
<b>7</b>	<b>Storage, Manufacturing and Packaging.....</b>	<b>58</b>
7.1.	Storage Conditions.....	58
7.2.	Manufacturing and Soldering.....	58
7.3.	Packaging Specification.....	60
7.3.1.	Carrier Tape .....	60
7.3.2.	Plastic Reel .....	61
7.3.3.	Mounting Direction .....	61
7.3.4.	Packaging Process .....	62
<b>8</b>	<b>Appendix References .....</b>	<b>63</b>
	<b>Document History .....</b>	<b>67</b>
	<b>FCC Statement.....</b>	<b>68</b>
	<b>IC Statement.....</b>	<b>69</b>

# Table Index

Table 1: Frequency Bands and Functions .....	9
Table 2: Key Features of the Module .....	9
Table 3: Parameter Definition .....	13
Table 4: Pin Description .....	14
Table 5: Overview of Operating Modes .....	18
Table 6: Pin Definition of VBAT and GND .....	22
Table 7: Pin Definition of PWRKEY .....	24
Table 8: Pin Definition of RESET_N .....	26
Table 9: Pin Definition of (U)SIM Interfaces .....	28
Table 10: Pin Definition of USB Interface .....	30
Table 11: Pin Definition of Main UART Interface .....	31
Table 12: Pin Definition of Debug UART Interface .....	31
Table 13: Pin Definition of PCM and I2C Interfaces .....	34
Table 14: Pin Definition of SPI Interface .....	35
Table 15: Pin Definition of Network Status Indication .....	35
Table 16: Working State of Network Status Indication .....	35
Table 17: Pin Definition of STATUS .....	36
Table 18: Default Behaviors of RI .....	37
Table 19: Pin Definition of ADC Interface .....	37
Table 20: Characteristics of ADC Interface .....	37
Table 21: Pin Definition of USB_BOOT Interface .....	38
Table 22: Pin Definition of RF Antenna .....	40
Table 23: Module Operating Frequencies .....	40
Table 24: Tx Power .....	41
Table 25: Conducted RF Receiver Sensitivity .....	41
Table 26: Pin Definition of GNSS Antenna Interface .....	42
Table 27: GNSS Frequency .....	43
Table 28: GNSS Performance .....	43
Table 29: Antenna Requirements .....	46
Table 30: Absolute Maximum Ratings .....	49
Table 31: Power Supply Ratings .....	49
Table 32: Operating and Storage Temperatures .....	50
Table 33: Power Consumption .....	50
Table 34: GNSS Power Consumption .....	51
Table 35: Electrostatic Discharge Characteristics (Temperature: 25 - 30 °C, Humidity: 40 ± 5 %) .....	52
Table 36: Recommended Thermal Profile Parameters .....	59
Table 37: Carrier Tape Dimension Table (Unit: mm) .....	60
Table 38: Plastic Reel Dimension Table (Unit: mm) .....	61
Table 39: Related Documents .....	63
Table 40: Terms and Abbreviations .....	63

# Figure Index

Figure 2: Pin Assignment (Top View) .....	13
Figure 3: Power Consumption in Sleep Mode .....	19
Figure 4: Sleep Mode Application via UART .....	20
Figure 5: Sleep Mode Application with USB Remote Wakeup .....	20
Figure 6: Sleep Mode Application with RI .....	21
Figure 7: Sleep Mode Application without Suspend Function .....	21
Figure 8: Star Structure of Power Supply .....	23
Figure 9: Reference Circuit of Power Supply .....	23
Figure 10: Turn On the Module Using Driving Circuit .....	24
Figure 11: Turn On the Module Using a Button .....	25
Figure 12: Turn-on Timing .....	25
Figure 13: Turn-off Timing .....	26
Figure 14: Reference Circuit of RESET_N by Using Driving Circuit .....	27
Figure 15: Reference Circuit of RESET_N by Using a Button .....	27
Figure 16: Reset Timing .....	27
Figure 17: Reference Circuit of (U)SIM Interface with an 8-pin (U)SIM Card Connector .....	29
Figure 18: Reference Circuit of (U)SIM Interface with a 6-pin (U)SIM Card Connector .....	29
Figure 19: Reference Circuit of USB Interface .....	30
Figure 20: Reference Circuit with Translator Chip .....	32
Figure 21: Reference Circuit with Transistor Circuit .....	32
Figure 22: Primary Mode Timing .....	33
Figure 23: Auxiliary Mode Timing .....	33
Figure 24: Reference Circuit of PCM Application with Audio Codec .....	34
Figure 25: Reference Circuit of SPI Interface with Peripheral .....	35
Figure 26: Reference Circuit of Network Status Indication .....	36
Figure 27: Reference Circuit of STATUS .....	36
Figure 28: Reference Circuit of USB_BOOT Interface .....	38
Figure 29: Timing of Entering Forced Download Mode .....	39
Figure 30: Reference Circuit of RF Antenna Interface .....	42
Figure 31: Reference Circuit of GNSS Antenna .....	44
Figure 32: Microstrip Design on a 2-layer PCB .....	45
Figure 33: Coplanar Waveguide Design on a 2-layer PCB .....	45
Figure 34: Coplanar Waveguide Design on a 4-layer PCB (Layer 3 as Reference Ground) .....	45
Figure 35: Coplanar Waveguide Design on a 4-layer PCB (Layer 4 as Reference Ground) .....	46
Figure 36: Dimensions of the Receptacle (Unit: mm) .....	47
Figure 37: Specifications of Mated Plugs .....	47
Figure 38: Space Factor of Mated Connectors (Unit: mm) .....	48
Figure 39: Referenced Heatsink Design (Heatsink at the Top of the Module) .....	53
Figure 40: Referenced Heatsink Design (Heatsink at the Backside of Customers' PCB) .....	53
Figure 41: Top and Side Dimensions .....	54
Figure 42: Bottom Dimensions (Top View) .....	55
Figure 43: Recommended Footprint .....	56
Figure 44: Top and Bottom Views of the Module .....	57
Figure 45: Recommended Reflow Soldering Thermal Profile .....	59
Figure 46: Carrier Tape Dimension Drawing (Unit: mm) .....	60
Figure 47: Plastic Reel Dimension Drawing .....	61
Figure 48: Mounting Direction .....	62
Figure 49: Packaging Process .....	62



# 1 Introduction

This document defines the LUH23-LD and describes its air interface and hardware interfaces which are connected with your applications.

This document can help you quickly understand module interface specifications, electrical and mechanical details, as well as other related information of the module. With application note and user guide, you can use the module to design and set up mobile applications easily.

## 2 Product Overview

### 2.1. Frequency Bands and Functions

LUH23-LD is an embedded LTE/WCDMA wireless communication module with receive diversity. It supports data connectivity on LTE-FDD, DC-HSDPA, HSPA+, HSDPA, HSUPA, WCDMA networks.

The following table shows the supported frequency bands and GNSS functions of the module.

*Table 1: Frequency Bands and Functions*

Module	LTE Band (with Rx-diversity)	WCDMA (with Rx-diversity)	GNSS (Optional)
LUH23-LD	FDD: B2/B4/B5/B12/B13/ B25/B26	B2/B4/B5	GPS, GLONASS, BDS, Galileo, QZSS

LUH23-LD is an SMD type module which can be embedded into applications through its 106 LGA pins. With a compact profile of 29.0 mm × 25.0 mm × 2.45 mm, it can meet almost all requirements for M2M applications.

The module is integrated with internet service protocols like TCP, UDP and PPP. Extended AT commands have been developed for you to use these internet service protocols easily.

### 2.2. Key Features

The following table describes the detailed features of the module.

*Table 2: Key Features of the Module*

Feature	Details
Power Supply	<ul style="list-style-type: none"> <li>Supply voltage range: 3.3–4.3 V</li> <li>Typical supply voltage: 3.8 V</li> </ul>
Transmitting Power	<ul style="list-style-type: none"> <li>Class 3 (23 dBm ±2 dB) for WCDMA bands</li> <li>Class 3 (23 dBm ±2 dB) for LTE-FDD bands</li> </ul>
LTE Features	<ul style="list-style-type: none"> <li>Support up to non-CA Cat 4 FDD</li> <li>Support 1.4/3/5/10/15/20 MHz RF bandwidths</li> <li>Modulations: <ul style="list-style-type: none"> <li>DL: QPSK, 16QAM and 64QAM</li> <li>UL: QPSK and 16QAM</li> </ul> </li> <li>LTE-FDD: Max. 150 Mbps (DL), Max. 50 Mbps (UL)</li> </ul>
UMTS Features	<ul style="list-style-type: none"> <li>Support 3GPP Rel-8 DC-HSDPA, HSPA+, HSDPA, HSUPA and WCDMA</li> <li>Support QPSK, 16QAM and 64QAM modulations</li> <li>DC-HSDPA: Max. 42 Mbps (DL)</li> <li>HSUPA: Max. 5.76 Mbps (UL)</li> <li>WCDMA: Max. 384 kbps (DL), Max. 384 kbps (UL)</li> </ul>
Internet Protocol Features	<ul style="list-style-type: none"> <li>Support TCP/UDP/PPP/FTP/FTPS/HTTP/HTTPS/NTP/PING/QMI/NITZ/MMS/SMTP/SSL/MQTT/FILE/CMUX/SMTPS protocols</li> <li>Support PAP and CHAP protocols for PPP connections</li> </ul>

SMS	<ul style="list-style-type: none"> <li>● Text and PDU modes</li> <li>● Point-to-point MO and MT</li> <li>● SMS cell broadcast</li> <li>● SMS storage: ME by default</li> </ul>
(U)SIM Interfaces	<ul style="list-style-type: none"> <li>● Support 1.8 V and 3.0 V (U)SIM cards</li> <li>● Support Dual SIM Single Standby</li> </ul>
Audio Features	<ul style="list-style-type: none"> <li>● Support one digital audio interface: PCM interface</li> <li>● WCDMA: AMR/AMR-WB</li> <li>● LTE: AMR/AMR-WB</li> </ul>
PCM Interface	<ul style="list-style-type: none"> <li>● Used for audio function with external codec</li> <li>● Support 16-bit linear data format</li> <li>● Support long frame synchronization and short frame synchronization</li> <li>● Support master and slave mode, but must be the master in long frame synchronization</li> </ul>
USB Interface	<ul style="list-style-type: none"> <li>● Compliant with USB 2.0 specification (slave mode only); the data transmission rate can reach up to 480 Mbps</li> <li>● Used for AT command communication, data transmission, GNSS NMEA sentence output, software debugging and firmware upgrade</li> <li>● Support USB serial drivers for: Windows 7/8/8.1/10/11, Linux 2.6–6.7, Android 4.x–13.x, etc.</li> </ul>
UART Interfaces	<p><b>Main UART:</b></p> <ul style="list-style-type: none"> <li>● Used for AT command communication and data transmission</li> <li>● Baud rates reach up to 921600 bps, 115200 bps by default</li> <li>● Support RTS and CTS hardware flow control</li> </ul> <p><b>Debug UART:</b></p> <ul style="list-style-type: none"> <li>● Used for Linux console and log output</li> <li>● 115200 bps baud rate</li> </ul>
SPI Interface	<ul style="list-style-type: none"> <li>● Provides a duplex, synchronous and serial communication link with the peripheral devices.</li> <li>● Dedicated to one-to-one connection, without chip selection.</li> <li>● 1.8 V operation voltage with clock rates up to 50 MHz.</li> </ul>
Rx-diversity	Support LTE/WCDMA Rx-diversity
GNSS Features (Optional)	<ul style="list-style-type: none"> <li>● Protocol: NMEA 0183</li> <li>● Data update rate: 1 Hz by default</li> </ul>
AT Commands	<ul style="list-style-type: none"> <li>● Compliant with 3GPP TS 27.007 and 3GPP TS 27.005</li> <li>● Enhanced AT commands</li> </ul>
Network Indication	NETLIGHT pin for network activity status indication
Antenna Interfaces	<ul style="list-style-type: none"> <li>● Main antenna interface (ANT_MAIN)</li> <li>● Rx-diversity antenna interface (ANT_DIV)</li> <li>● GNSS antenna interface (ANT_GNSS)</li> </ul>
Physical Characteristics	<ul style="list-style-type: none"> <li>● Size: (29.0 ±0.15) mm × (25.0 ±0.15) mm × (2.45 ±0.2) mm</li> <li>● Package: LGA</li> <li>● Weight: approx. 4.2 g</li> </ul>
Temperature Ranges	<ul style="list-style-type: none"> <li>● Operating temperature range: -35 °C to +75 °C <sup>1</sup></li> <li>● Extended temperature range: -40 °C to +85 °C <sup>2</sup></li> <li>● Storage temperature range: -40 °C to +90 °C</li> </ul>

<sup>1</sup> To meet the normal operating temperature range requirements, it is necessary to ensure effective thermal dissipation, e.g., by adding passive or active heatsinks, heat pipes, vapor chambers. Within this range, the module's indicators comply with 3GPP specification requirements.

<sup>2</sup> To meet the extended operating temperature range requirements, it is necessary to ensure effective thermal dissipation, e.g., by adding passive or active heatsinks, heat pipes, vapor chambers. Within this range, the module remains the ability to establish and maintain functions such as SMS and data transmission, without any unrecoverable malfunction. Radio spectrum and radio network remain uninfluenced, whereas the value of one or more parameters, such as Pout, may decrease and fall below the range of the 3GPP specified tolerances. When the temperature returns to the normal operating temperature range, the module's indicators will comply with 3GPP specification requirements again.

---

Firmware Upgrade	<ul style="list-style-type: none"><li>● USB interface</li><li>● DFOTA</li></ul>
RoHS	All hardware components are fully compliant with EU RoHS directive

---

## 2.3. EVB Kit

NetPrisma supplies an evaluation board (UMTS&LTE EVB) with accessories to develop and test the module. For more details, see **document [1]**

# 3 Application Interfaces

## 3.1. General Description

The module is equipped with 106 LGA pins that can be connected to your cellular application platforms. The subsequent chapters will provide detailed descriptions of the following interfaces/functions.

- Power supply
- (U)SIM interfaces
- USB interface
- UART interfaces
- PCM and I2C interfaces
- SPI interface
- Indication signals
- ADC interface
- USB\_BOOT interface

## 3.2. Pin Assignment

The following figure shows the pin assignment of the module.

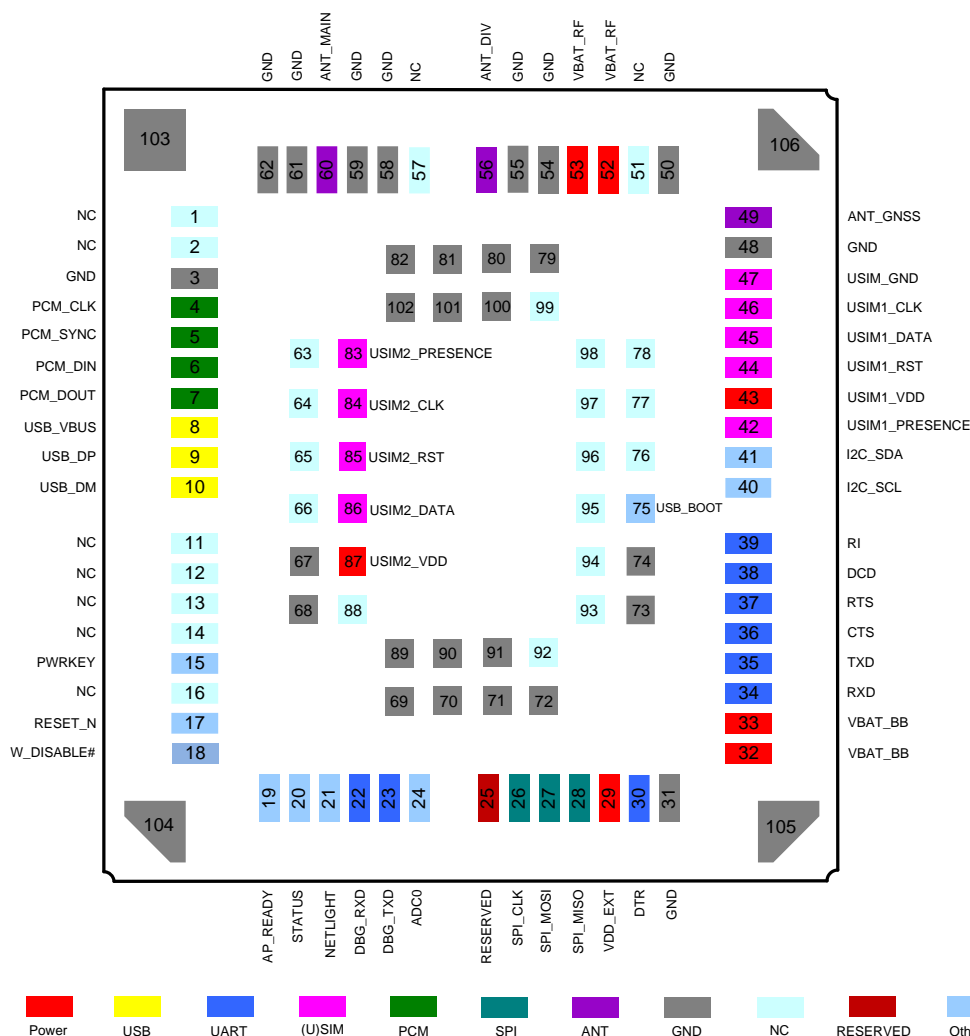


Figure 1: Pin Assignment (Top View)

## NOTE

1. PWRKEY output voltage is 0.8 V because of the diode drop in the baseband chipset.
2. Keep all RESERVED pins and unused pins unconnected.
3. GND pins should be connected to ground in the design.
4. Ensure that the pull-up power supply of the module's pins is VDD\_EXT or controlled by VDD\_EXT, and there is no current sink on the module's pins before the module turns on. For more details, contact NetPrisma Technical Support.

## 3.3. Pin Description

The following tables show the pin definition and description of the module.

Table 3: Parameter Definition

Parameter	Description
-----------	-------------

AI	Analog Input
AIO	Analog Input/Output
DI	Digital Input
DO	Digital Output
DIO	Digital Input/Output
OD	Open Drain
PI	Power Input
PO	Power Output

DC characteristics include power domain and rated current.

[Table 4: Pin Description](#)

Power Supply					
Pin Name	Pin No.	I/O	Description	DC Characteristics	Comment
VBAT_BB	32, 33	PI	Power supply for the module's BB part	Vmax = 4.3 V Vmin = 3.3 V Vnom = 3.8 V	It must be provided with sufficient current up to 0.8 A. A test point is recommended to be reserved.
VBAT_RF	52, 53	PI	Power supply for the module's RF part		It must be provided with sufficient current up to 1.8 A in a burst transmission. A test point is recommended to be reserved.
VDD_EXT	29	PO	Provide 1.8 V for external circuit	Vnom = 1.8 V Iomax = 50 mA	Power supply for external GPIO's pull up circuits. If unused, keep it open.
GND	3, 31, 48, 50, 54, 55, 58, 59, 61, 62, 67–74, 79–82, 89–91, 100–106				
Turn On/Off					
Pin Name	Pin No.	I/O	Description	DC Characteristics	Comment
PWRKEY	15	DI	Turn on/off the module	VIHmax = 2.1 V VIHmin = 1.3 V VILmax = 0.5 V	The output voltage is 0.8 V because of the diode drop in the baseband chipset. A test point is recommended to be reserved.
RESET_N	17	DI	Reset the module		Require pull-up resistor to 1.8 V internally. Active LOW. If unused, keep it open.
Status Indication					

Pin Name	Pin No.	I/O	Description	DC Characteristics	Comment
STATUS	20	DO	Indicate the module's operating status	V <sub>OHmin</sub> = 1.35 V V <sub>OLmax</sub> = 0.45 V	1.8 V power domain. If unused, keep them open.
NETLIGHT	21	DO	Indicate the module's network activity status		

### USB Interface

Pin Name	Pin No.	I/O	Description	DC Characteristics	Comment
USB_VBUS	8	AI	USB connection detect	V <sub>max</sub> = 5.25 V V <sub>min</sub> = 3.0 V V <sub>nom</sub> = 5.0 V	Typical value: 5.0 V If unused, keep it open.
USB_DP	9	AIO	USB differential data (+)		USB 2.0 compliant. Require differential impedance of 90 Ω.
USB_DM	10	AIO	USB differential data (-)		

### (U)SIM Interfaces

Pin Name	Pin No.	I/O	Description	DC Characteristics	Comment
USIM_GND	47	-	Specified ground for (U)SIM card		Connect to ground of (U)SIM card connector.
USIM1_VDD	43	PO	(U)SIM1 card power supply	I <sub>omax</sub> = 50 mA  <b>For 1.8 V (U)SIM:</b> V <sub>max</sub> = 1.9 V V <sub>min</sub> = 1.7 V  <b>For 3.0 V (U)SIM:</b> V <sub>max</sub> = 3.05 V V <sub>min</sub> = 2.7 V	Either 1.8 V or 3.0 V is supported by the module automatically.
USIM1_DATA	45	DIO	(U)SIM1 card data	<b>For 1.8 V (U)SIM:</b> V <sub>ILmax</sub> = 0.6 V V <sub>IHmin</sub> = 1.2 V V <sub>OLmax</sub> = 0.45 V V <sub>OHmin</sub> = 1.35 V  <b>For 3.0 V (U)SIM:</b> V <sub>ILmax</sub> = 1.0 V V <sub>IHmin</sub> = 1.95 V V <sub>OLmax</sub> = 0.45 V V <sub>OHmin</sub> = 2.55 V	
USIM1_CLK	46	DO	(U)SIM1 card clock	<b>For 1.8 V (U)SIM:</b> V <sub>OLmax</sub> = 0.45 V V <sub>OHmin</sub> = 1.35 V	
USIM1_RST	44	DO	(U)SIM1 card reset	<b>For 3.0 V (U)SIM:</b> V <sub>OLmax</sub> = 0.45 V V <sub>OHmin</sub> = 2.55 V	
USIM1_PRESENCE	42	DI	(U)SIM1 card hot-plug detect	V <sub>ILmin</sub> = -0.3 V V <sub>ILmax</sub> = 0.6 V V <sub>IHmin</sub> = 1.2 V V <sub>IHmax</sub> = 2.0 V  I <sub>omax</sub> = 50 mA	1.8 V power domain. If unused, keep it open.
USIM2_VDD	87	PO	(U)SIM2 card power supply	<b>For 1.8 V (U)SIM:</b> V <sub>max</sub> = 1.9 V V <sub>min</sub> = 1.7 V  <b>For 3.0 V (U)SIM:</b>	Either 1.8 V or 3.0 V is supported by the module automatically. If unused, keep it open.



				V <sub>max</sub> = 3.05 V V <sub>min</sub> = 2.7 V	
USIM2_DATA	86	DIO	(U)SIM2 card data	<b>For 1.8 V (U)SIM:</b> V <sub>ILmax</sub> = 0.6 V V <sub>IHmin</sub> = 1.2 V V <sub>OLmax</sub> = 0.45 V V <sub>OHmin</sub> = 1.35 V  <b>For 3.0 V (U)SIM:</b> V <sub>ILmax</sub> = 1.0 V V <sub>IHmin</sub> = 1.95 V V <sub>OLmax</sub> = 0.45 V V <sub>OHmin</sub> = 2.55 V	
USIM2_CLK	84	DO	(U)SIM2 card clock	<b>For 1.8 V (U)SIM:</b> V <sub>OLmax</sub> = 0.45 V V <sub>OHmin</sub> = 1.35 V  <b>For 3.0 V (U)SIM:</b> V <sub>OLmax</sub> = 0.45 V V <sub>OHmin</sub> = 2.55 V	If unused, keep them open.
USIM2_RST	85	DO	(U)SIM2 card reset	<b>For 1.8 V (U)SIM:</b> V <sub>OLmax</sub> = 0.45 V V <sub>OHmin</sub> = 1.35 V  <b>For 3.0 V (U)SIM:</b> V <sub>OLmax</sub> = 0.45 V V <sub>OHmin</sub> = 2.55 V	
USIM2_PRESENCE	83	DI	(U)SIM2 card hot-plug detect	V <sub>ILmin</sub> = -0.3 V V <sub>ILmax</sub> = 0.6 V V <sub>IHmin</sub> = 1.2 V V <sub>IHmax</sub> = 2.0 V	1.8 V power domain. If unused, keep it open.

### Main UART Interface

Pin Name	Pin No.	I/O	Description	DC Characteristics	Comment
RI	39	DO	Ring indication		1.8 V power domain. If unused, keep them open.
DCD	38	DO	Data carrier detect	V <sub>OLmax</sub> = 0.45 V V <sub>OHmin</sub> = 1.35 V	Connect to the MCU's CTS.
CTS	36	DO	Clear to send signal from the module		1.8 V power domain. If unused, keep it open.
RTS	37	DI	Request to send signal to the module	V <sub>ILmin</sub> = -0.3 V V <sub>ILmax</sub> = 0.6 V V <sub>IHmin</sub> = 1.2 V V <sub>IHmax</sub> = 2.0 V	Connect to the MCU's RTS. 1.8 V power domain. If unused, keep it open.
DTR	30	DI	Data terminal ready Sleep mode control		1.8 V power domain. Pulled up by default. Low level wakes up the module. If unused, keep it open.
TXD	35	DO	Transmit	V <sub>OLmax</sub> = 0.45 V V <sub>OHmin</sub> = 1.35 V	
RXD	34	DI	Receive	V <sub>ILmin</sub> = -0.3 V V <sub>ILmax</sub> = 0.6 V V <sub>IHmin</sub> = 1.2 V V <sub>IHmax</sub> = 2.0 V	1.8 V power domain. If unused, keep them open.

### Debug UART Interface

Pin Name	Pin No.	I/O	Description	DC Characteristics	Comment
----------	---------	-----	-------------	--------------------	---------

DBG_TXD	23	DO	Debug UART transmit	$V_{OLmax} = 0.45\text{ V}$ $V_{OHmin} = 1.35\text{ V}$	1.8 V power domain. If unused, keep them open.
DBG_RXD	22	DI	Debug UART receive	$V_{ILmin} = -0.3\text{ V}$ $V_{ILmax} = 0.6\text{ V}$ $V_{IHmin} = 1.2\text{ V}$ $V_{IHmax} = 2.0\text{ V}$	

### PCM Interface

Pin Name	Pin No.	I/O	Description	DC Characteristics	Comment
PCM_DIN	6	DI	PCM data input	$V_{ILmin} = -0.3\text{ V}$ $V_{ILmax} = 0.6\text{ V}$ $V_{IHmin} = 1.2\text{ V}$ $V_{IHmax} = 2.0\text{ V}$	1.8 V power domain. If unused, keep them open.
PCM_DOUT	7	DO	PCM data output	$V_{OLmax} = 0.45\text{ V}$ $V_{OHmin} = 1.35\text{ V}$	
PCM_SYNC	5	DIO	PCM data frame sync	$V_{OLmax} = 0.45\text{ V}$ $V_{OHmin} = 1.35\text{ V}$ $V_{ILmin} = -0.3\text{ V}$ $V_{ILmax} = 0.6\text{ V}$ $V_{IHmin} = 1.2\text{ V}$ $V_{IHmax} = 2.0\text{ V}$	1.8 V power domain. In master mode, they are output signals. In slave mode, they are input signals. If unused, keep them open.
PCM_CLK	4	DIO	PCM clock		

### I2C Interface

Pin Name	Pin No.	I/O	Description	DC Characteristics	Comment
I2C_SCL	40	OD	I2C serial clock (for external codec)		Require an external pull-up to 1.8 V If unused, keep them open.
I2C_SDA	41	OD	I2C serial data (for external codec)		

### ADC Interface

Pin Name	Pin No.	I/O	Description	DC Characteristics	Comment
ADC0	24	AI	General-purpose ADC interface	Voltage range: 0.3 V to VBAT_BB	If unused, keep it open.

### SPI Interface

Pin Name	Pin No.	I/O	Description	DC Characteristics	Comment
SPI_CLK	26	DO	SPI clock	$V_{OLmax} = 0.45\text{ V}$ $V_{OHmin} = 1.35\text{ V}$	1.8 V power domain. If unused, keep them open.
SPI_MOSI	27	DO	SPI master-out slave-in		
SPI_MISO	28	DI	SPI master-in slave-out	$V_{ILmin} = -0.3\text{ V}$ $V_{ILmax} = 0.6\text{ V}$ $V_{IHmin} = 1.2\text{ V}$ $V_{IHmax} = 2.0\text{ V}$	

### RF Interfaces

Pin Name	Pin No.	I/O	Description	DC Characteristics	Comment
ANT_GNSS	49	AI	GNSS antenna interface		50 $\Omega$ impedance. If unused, keep them open.
ANT_DIV	56	AI	Diversity antenna interface		
ANT_MAIN	60	AIO	Main antenna Interface		50 $\Omega$ impedance.

### Other Pins

Pin Name	Pin No.	I/O	Description	DC Characteristics	Comment
W_DISABLE#	18	DI	Airplane mode control	$V_{ILmin} = -0.3\text{ V}$ $V_{ILmax} = 0.6\text{ V}$ $V_{IHmin} = 1.2\text{ V}$ $V_{IHmax} = 2.0\text{ V}$	1.8 V power domain. Pulled up by default. At low voltage level, module can enter airplane mode. If unused, keep it open.
AP_READY	19	DI	Application processor ready		1.8 V power domain. If unused, keep it open.
USB_BOOT	75	DI	Force the module to enter download mode		1.8 V power domain. Active HIGH. A test point is recommended to reserved.

### NC and RESERVED Pins

Pin Name	Pin No.	Comment
NC	1, 2, 11–14, 16, 51, 57, 63–66, 76–78, 88, 92–99	Keep them unconnected.
RESERVED	25	

### NOTE

1. Keep all RESERVED pins and unused pins unconnected.
2. USB\_BOOT pin and BOOT\_CONFIG pins (SPI\_CLK, PCM\_CLK and PCM\_SYNC) cannot be pulled up before startup.

## 3.4. Operating Modes

The table below briefly outlines the operating modes to be mentioned in the following chapters.

*Table 5: Overview of Operating Modes*

Mode	Details	
Full Functionality Mode	Idle	Software is active. The module has registered on network, and it is ready to send and receive data.
	Data	Network is connected. In this mode, the power consumption is decided by network setting and data transmission rate.
Airplane Mode	<b>AT+CFUN=4</b> or W_DISABLE# pin can set the module to enter airplane mode. In this case, RF function will be invalid.	

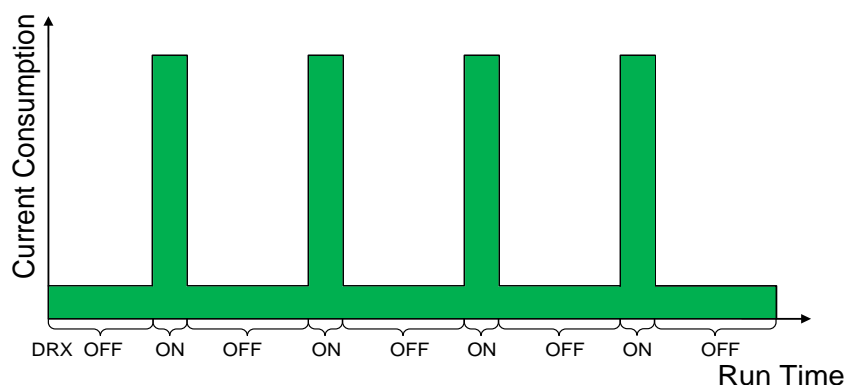
Minimum Functionality Mode	<b>AT+CFUN=0</b> can set the module to a minimum functionality mode without removing the power supply. In this case, both RF function and (U)SIM card will be invalid.
Sleep Mode	In this mode, the power consumption of the module will be reduced to an ultra-low level. During this mode, the module can still receive paging message, SMS and TCP/UDP data from the network normally.
Power Down Mode	In this mode, the power management unit shuts down the power supply. Software goes inactive. The serial interface is not accessible. Operating voltage (connected to VBAT_RF and VBAT_BB) remains applied.

For details of the above AT command, see *document [2]*.

## 3.5. Power Saving

### 3.5.1. Sleep Mode

The module is able to reduce its power consumption to an ultra-low level during the sleep mode. The following sub-chapters describe the power saving procedures of the module.



*Figure 2: Power Consumption in Sleep Mode*

#### NOTE

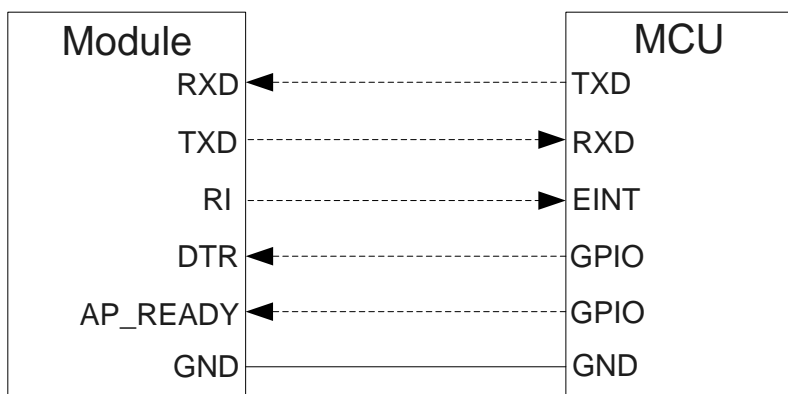
DRX cycle values are transmitted over the wireless network.

#### 3.5.1.1. UART Application Scenario

If the MCU communicates with the module via UART interface, the following preconditions can let the module enter sleep mode.

- Execute **AT+QSCLK=1** to enable sleep mode.
- Drive DTR to high level.

The following figure shows the connection between the module and the MCU.



*Figure 3: Sleep Mode Application via UART*

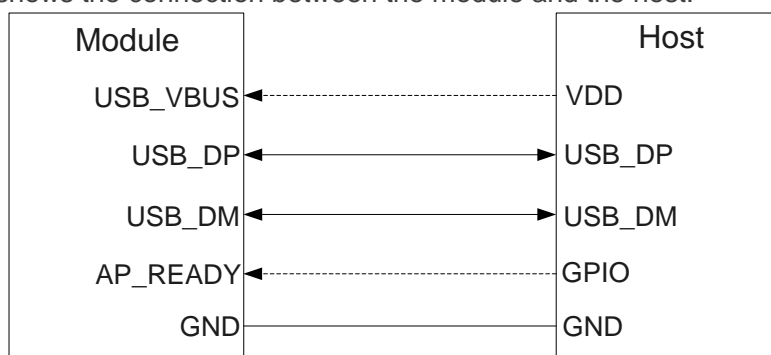
- Driving the module's DTR to low level will wake up the module.
- When the module has a URC to report, RI signal will wake up the MCU. See **Chapter 3.15.3** for details about RI behaviors.
- AP\_READY will detect the sleep state of the MCU (can be configured to high-level or low-level detection). See **document [3]** for details about **AT+QCFG="apready"**.

### 3.5.1.2. USB Application with USB Remote Wakeup Function

If the host supports USB Suspend/Resume and remote wakeup functions, the following three preconditions must be met to let the module enter sleep mode.

- Execute **AT+QSClk=1** to enable sleep mode.
- Ensure the DTR is held at high level or keep it open.
- The host's USB bus, which is connected with the module's USB interface, enters Suspend state.

The following figure shows the connection between the module and the host.



*Figure 4: Sleep Mode Application with USB Remote Wakeup*

- Sending data to the module through USB will wake up the module.
- When the module has a URC to report, it will send remote wakeup signals via USB bus to wake up the host.

### 3.5.1.3. USB Application with USB Suspend/Resume and RI Function

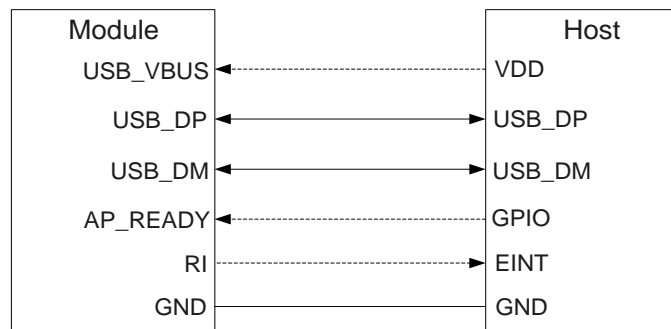
If the host supports USB Suspend/Resume, but does not support remote wakeup function, the RI signal is needed to wake up the host.

There are three preconditions to let the module enter sleep mode.

- Execute **AT+QSClk=1** to enable sleep mode.

- Ensure the DTR is held at high level or keep it open.
- The host's USB bus, which is connected with the module's USB interface, enters Suspended state.

The following figure shows the connection between the module and the host.



*Figure 5: Sleep Mode Application with RI*

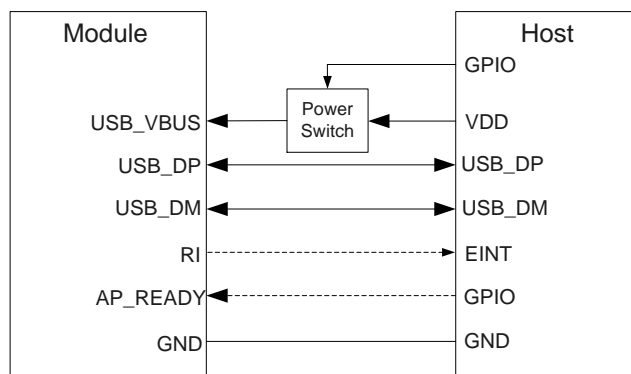
- Sending data to the module through USB will wake up the module.
- When the module has a URC to report, RI signal will wake up the host.

#### 3.5.1.4. USB Application without USB Suspend Function

If the host does not support USB Suspend function, USB\_VBUS should be disconnected with an external control circuit to let the module enter sleep mode.

- Execute **AT+QSCLK=1** to enable sleep mode.
- Ensure the DTR is held at high level or keep it open.
- Disconnect USB\_VBUS.

The following figure shows the connection between the module and the host.



*Figure 6: Sleep Mode Application without Suspend Function*

Switching on the power switch to supply power to USB\_VBUS will wake up the module.

## NOTE

1. Pay attention to the level-matching shown in dotted line between the module and the host.
2. For more details about the module power management application, see **document [4]**.
3. For details of **AT+QSCLK**, see **document [2]**.
4. For details of **AT+QCFG**, see **document [3]**.

### 3.5.2. Airplane Mode

When the module enters airplane mode, the RF function will be disabled, and all AT commands related to it will be inaccessible. This mode can be set via the following ways.

#### Hardware:

The W\_DISABLE# pin is pulled up by default. Driving it to low level will let the module enter airplane mode.

#### Software:

**AT+CFUN=<fun>** provides the choice of the functionality level through setting <fun> as 0, 1 or 4. See **document [2]** for more details.

- **AT+CFUN=0:** Minimum functionality mode. Both (U)SIM and RF functions are disabled.
- **AT+CFUN=1:** Full functionality mode (by default).
- **AT+CFUN=4:** Airplane mode (RF function is disabled).

### NOTE

1. Airplane mode control via W\_DISABLE# is disabled in firmware by default. It can be enabled by **AT+QCFG="airplanecontrol"**. See **document [3]** for more details.
2. The execution of **AT+CFUN** will not affect GNSS function.

## 3.6. Power Supply

### 3.6.1. Power Supply Pins

The module provides four VBAT pins for connection with an external power supply. There are two separate voltage domains for VBAT.

- Two VBAT\_RF pins for module's RF part.
- Two VBAT\_BB pins for module's BB part.

The following table shows the details of VBAT pins and ground pins.

*Table 6: Pin Definition of VBAT and GND*

Pin Name	Pin No.	Description	Min.	Typ.	Max.	Unit
VBAT_RF	52, 53	Power supply for the module's RF part.	3.3	3.8	4.3	V
VBAT_BB	32, 33	Power supply for the module's BB part.	3.3	3.8	4.3	V
GND	3, 31, 48, 50, 54, 55, 58, 59, 61, 62, 67–74, 79–82, 89–91, 100–106					

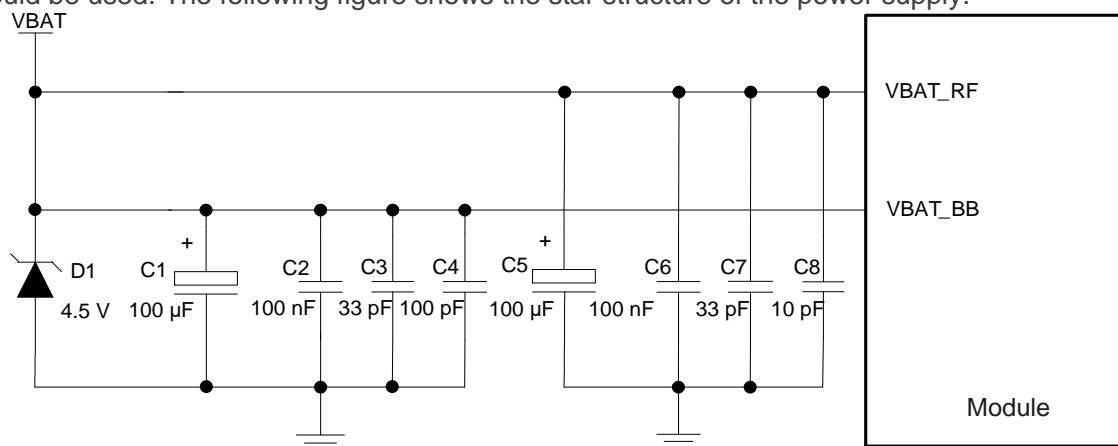
### 3.6.2. Voltage Stability Requirements

The power supply range of the module is from 3.3 V to 4.3 V. Make sure that the input voltage will never drop below 3.3 V.

To decrease voltage drop, a filter capacitor of about 100  $\mu$ F with low ESR (ESR = 0.7  $\Omega$ ) should be used for VBAT\_BB and VBAT\_RF respectively, and a multi-layer ceramic chip (MLCC) capacitor array should

also be reserved due to its ultra-low ESR. It is recommended to use three ceramic capacitors (100 nF, 33 pF, 100 pF for VBAT\_BB and 100 nF, 33 pF, 10 pF for VBAT\_RF) for composing the MLCC array, and place these capacitors close to VBAT\_BB/VBAT\_RF pins. The main power supply from an external application has to be a single voltage source and can be expanded to two sub paths with star structure. The width of VBAT\_BB trace should be not less than 1 mm, and the width of VBAT\_RF trace should be not less than 2 mm. In principle, the longer the VBAT trace is, the wider it should be.

In addition, to avoid the damage caused by electric surge and ESD, it is suggested that a TVS diode with low reverse stand-off voltage  $V_{RWM}$  (4.5 V), low clamping voltage  $V_C$  and high reverse peak pulse current  $I_{PP}$  should be used. The following figure shows the star structure of the power supply.

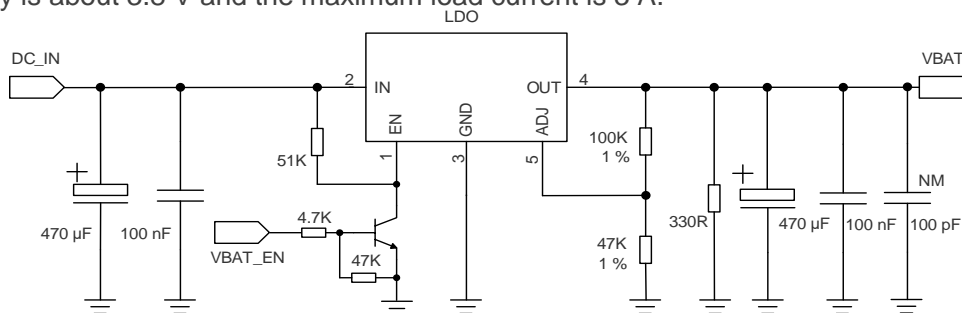


*Figure 7: Star Structure of Power Supply*

### 3.6.3. Reference Design for Power Supply

Power design for the module is very important, as the performance of the module largely depends on the power source. The power supply should be able to provide sufficient current up to 1.5 A at least. If the voltage drop between the input and output is not too high, it is suggested that an LDO should be used to supply power for the module. If there is a big voltage difference between the input source and the desired output (VBAT), a buck converter is preferred to be used as the power supply.

The following figure shows a reference design for +5 V input power source. The typical output of the power supply is about 3.8 V and the maximum load current is 3 A.



*Figure 8: Reference Circuit of Power Supply*

### NOTE

To avoid corrupting the data in the internal flash, do not switch off the power supply when the module works normally. Only after the module is shut down by PWRKEY or AT command, then the power supply can be cut off.



### 3.6.4. Power Supply Voltage Monitoring

AT+CBC can be used to monitor the VBAT\_BB voltage value. For more details, see [document \[2\]](#).

## 3.7. Turn On

### 3.7.1. Turn On with PWRKEY

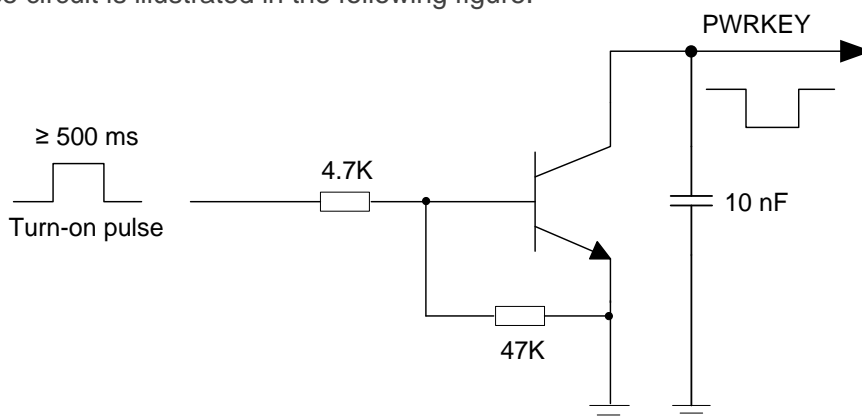
The following table shows the pin definition of PWRKEY.

*Table 7: Pin Definition of PWRKEY*

Pin Name	Pin No.	Description	Comment
PWRKEY	15	Turn on/off the module	The output voltage is 0.8 V because of the diode drop in the baseband chipset.

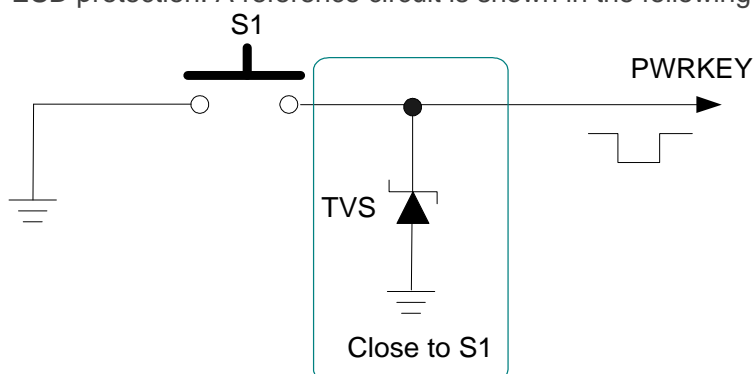
When the module is in power-down mode, it can be turned on to full functionality mode by driving PWRKEY low for at least 500 ms. It is recommended to use an open drain/collector driver to control the PWRKEY, and release PWRKEY after STATUS outputs a high level. The STATUS pin is used as an indicator to show that the module has been turned on normally.

A simple reference circuit is illustrated in the following figure.



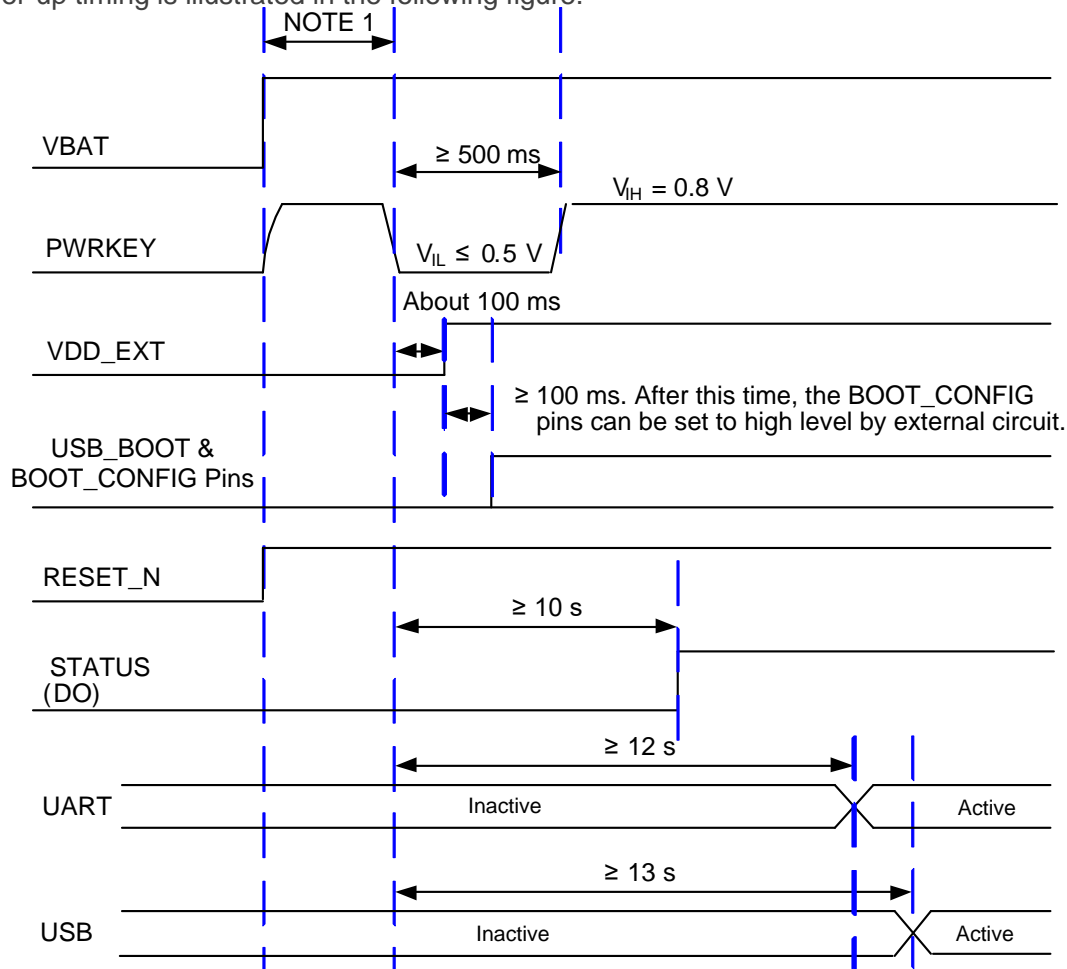
*Figure 9: Turn On the Module Using Driving Circuit*

Another way to control the PWRKEY is using a button directly. When pressing the button, electrostatic strike may be generated from the finger. Therefore, a TVS component is indispensable to be placed nearby the button for ESD protection. A reference circuit is shown in the following figure.



*Figure 10: Turn On the Module Using a Button*

The power-up timing is illustrated in the following figure.



*Figure 11: Turn-on Timing*

## NOTE

1. Make sure that VBAT is stable before pulling down PWRKEY pin. It is recommended that the time between powering up VBAT and pulling down PWRKEY pin is not less than 30 ms.
2. PWRKEY can be pulled down directly to GND with a recommended 10 k $\Omega$  resistor if the module needs to be powered on automatically and shutdown is not needed.
3. USB\_BOOT pin and BOOT\_CONFIG pins (SPI\_CLK, PCM\_CLK and PCM\_SYNC) cannot be pulled up before startup.

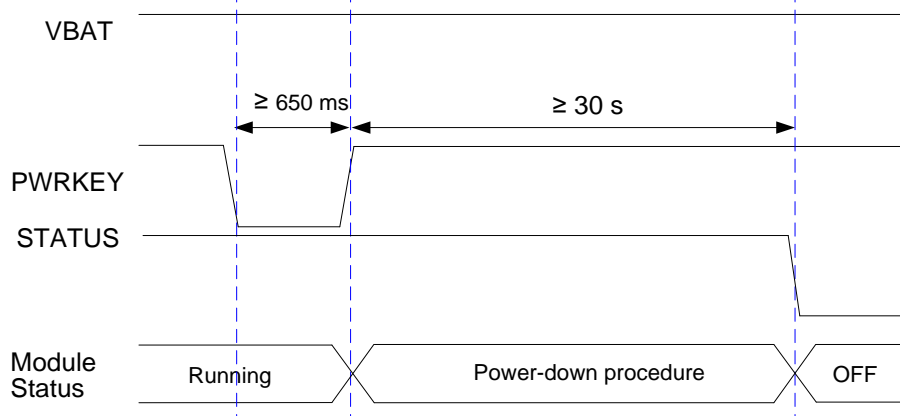
## 3.8. Turn Off

Either of the following methods can be used to turn off the module normally:

- Use the PWRKEY pin.
- Use **AT+QPOWD**

### 3.8.1. Turn Off with PWRKEY

Driving PWRKEY low for at least 650 ms, the module will execute power-down procedure after the PWRKEY is released. The power-down timing is illustrated in the following figure.



*Figure 12: Turn-off Timing*

### 3.8.2. Turn Off with AT Command

It is also a safe way to use **AT+QPOWD** to turn off the module, which is similar to turning off the module via PWRKEY pin.

See **document [2]** for details about the **AT+QPOWD**.

#### NOTE

1. To avoid corrupting the data in the internal flash, do not switch off the power supply when the module works normally. Only after the module is shut down by PWRKEY or AT command, the power supply can be cut off.
2. When turning off module with the AT command, keep PWRKEY at high level after the execution of the command. Otherwise, the module will be turned on automatically again after successfully turn-off.

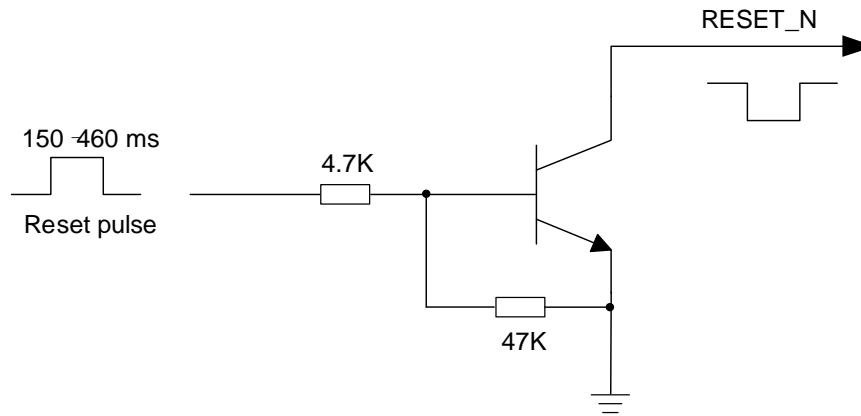
## 3.9. Reset

The RESET\_N pin can be used to reset the module. The module can be reset by driving RESET\_N low for 150–460 ms.

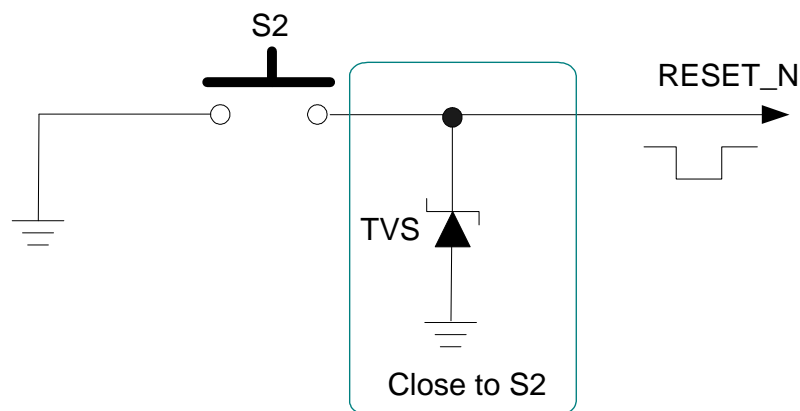
*Table 8: Pin Definition of RESET\_N*

Pin Name	Pin No.	Description	Comment
RESET_N	17	Reset the module	Require pull-up resistor to 1.8 V internally. Active low. If unused, keep it open.

The recommended circuit is similar to the PWRKEY control circuit. An open drain/collector driver or button can be used to control the RESET\_N.

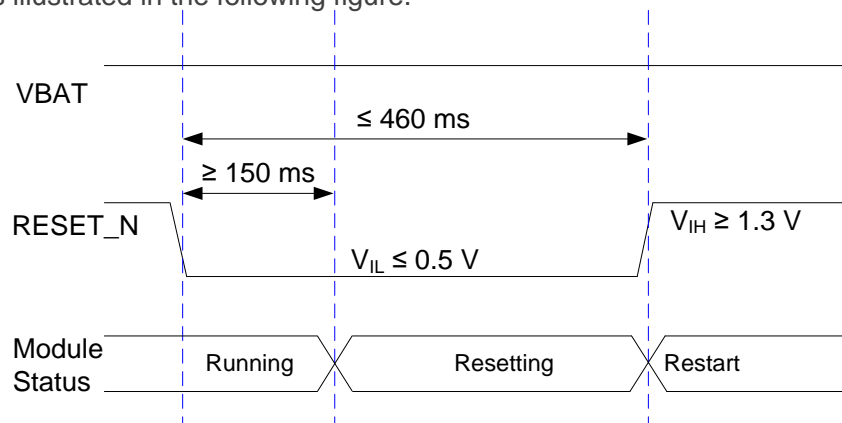


*Figure 13: Reference Circuit of RESET\_N by Using Driving Circuit*



*Figure 14: Reference Circuit of RESET\_N by Using a Button*

The reset timing is illustrated in the following figure.



*Figure 15: Reset Timing*

## NOTE

1. Use RESET\_N only when turning off the module by **AT+QPOWD** and PWRKEY pin are failed.
2. Ensure that there is no large capacitance on PWRKEY and RESET\_N pins.

### 3.10. (U)SIM Interfaces

The module provides two (U)SIM interfaces, and only one (U)SIM card can work at a time. The (U)SIM1 and (U)SIM2 cards can be switched by **AT+QDSIM**. For more details, see **document [5]**.

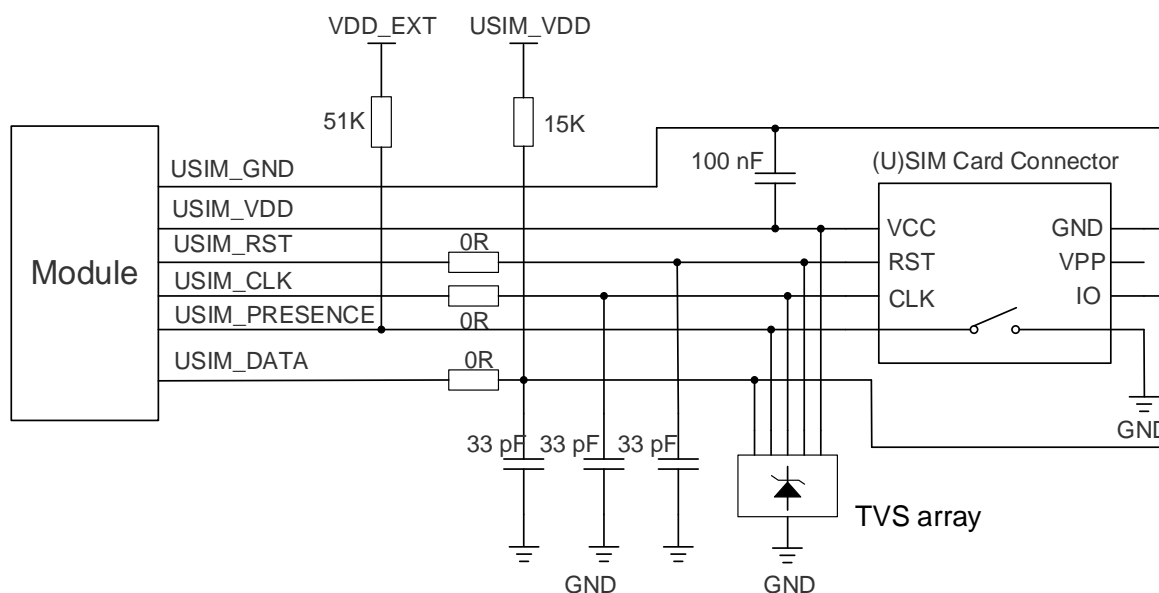
The (U)SIM interfaces circuitry meets ETSI and IMT-2000 requirements. Both 1.8 V and 3.0 V (U)SIM cards are supported.

*Table 9: Pin Definition of (U)SIM Interfaces*

Pin Name	Pin No.	I/O	Description	Comment
USIM_GND	47	-	Specified ground for (U)SIM card	Connect to ground of (U)SIM card connector.
USIM1_VDD	43	PO	(U)SIM1 card power supply	Either 1.8 V or 3.0 V is supported by the module automatically.
USIM1_DATA	45	DIO	(U)SIM1 card data	
USIM1_CLK	46	DO	(U)SIM1 card clock	
USIM1_RST	44	DO	(U)SIM1 card reset	
USIM1_PRESENCE	42	DI	(U)SIM1 card hot-plug detect	1.8 V power domain. If unused, keep it open.
USIM2_VDD	87	PO	(U)SIM2 card power supply	Either 1.8 V or 3.0 V is supported by the module automatically. If unused, keep it open.
USIM2_DATA	86	DIO	(U)SIM2 card data	
USIM2_CLK	84	DO	(U)SIM2 card clock	If unused, keep them open.
USIM2_RST	85	DO	(U)SIM2 card reset	
USIM2_PRESENCE	83	DI	(U)SIM2 card hot-plug detect	1.8 V power domain. If unused, keep it open.

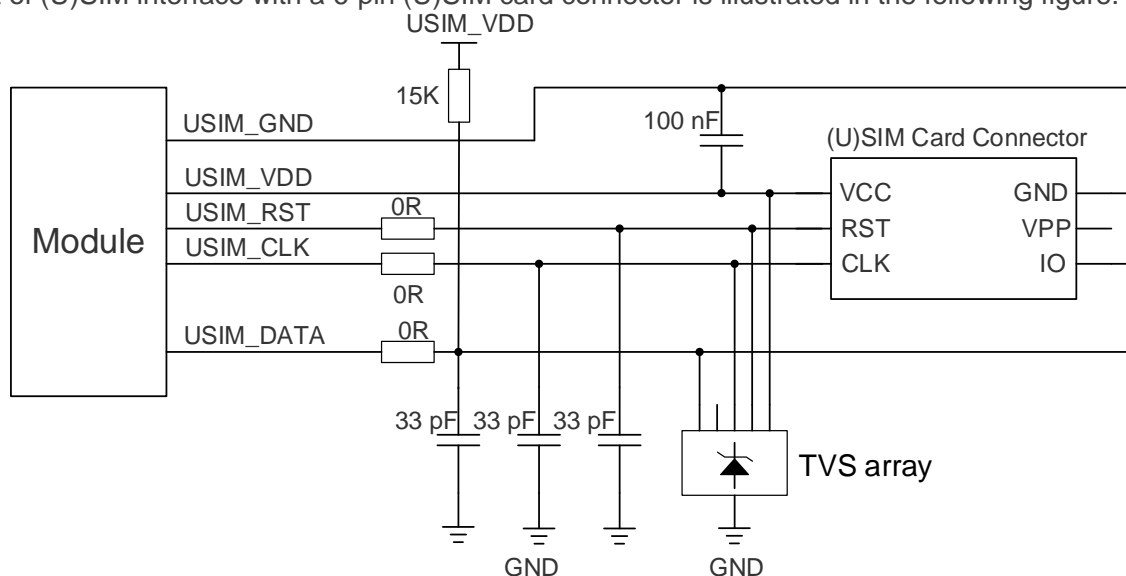
The module supports (U)SIM card hot-plug via USIM\_PRESENCE pin, and both high-level and low-level detection are supported. The function is disabled by default, and see **document [2]** for more details about **AT+QSIMDET**.

The following figure shows a reference design for (U)SIM interface with an 8-pin (U)SIM card connector.



*Figure 16: Reference Circuit of (U)SIM Interface with an 8-pin (U)SIM Card Connector*

If (U)SIM card detection function is not needed, keep USIM\_PRESENCE unconnected. A reference circuit of (U)SIM interface with a 6-pin (U)SIM card connector is illustrated in the following figure.



*Figure 17: Reference Circuit of (U)SIM Interface with a 6-pin (U)SIM Card Connector*

To enhance the reliability and availability of the (U)SIM cards in your applications, follow the criteria below in the (U)SIM circuit design:

- Keep placement of (U)SIM card connector to the module as close as possible. Keep the trace length as short as possible, at most 200 mm.
- Keep (U)SIM card signals away from RF and power supply traces.
- Make sure the bypass capacitor between USIM\_VDD and USIM\_GND less than 1  $\mu$ F, and place it as close to (U)SIM card connector as possible. If the ground is complete on your PCB, USIM\_GND can be connected to PCB ground directly.
- To avoid cross-talk between USIM\_DATA and USIM\_CLK, keep them away from each other and shield them with surrounded ground.
- For better ESD protection, it is recommended to add a TVS array whose parasitic capacitance should be less than 15 pF. The 0  $\Omega$  resistors should be added in series between the module and the (U)SIM card to facilitate debugging. Additionally, add 33 pF capacitors in parallel among USIM\_DATA,

USIM\_CLK and USIM\_RST signal traces to filter out RF interference. Note that the (U)SIM peripheral circuit should be close to the (U)SIM card connector.

- The pull-up resistor on USIM\_DATA trace can improve anti-jamming capability when long layout trace and sensitive occasion are applied, and should be placed close to the (U)SIM card connector.

### 3.11. USB Interface

The module contains one integrated Universal Serial Bus (USB) interface which complies with the USB 2.0 specification and supports high-speed (480 Mbps) and full-speed (12 Mbps) modes.

The USB interface can only serve as a slave device and is used for AT command communication, data transmission, GNSS NMEA sentence output, software debugging and firmware upgrade.

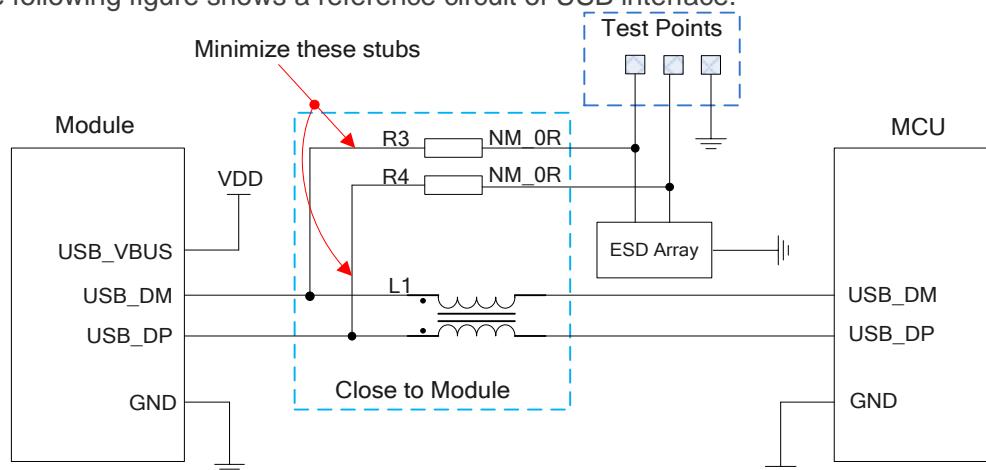
The following table shows the pin definition of USB interface.

*Table 10: Pin Definition of USB Interface*

Pin Name	Pin No.	I/O	Description	Comment
USB_DP	9	AIO	USB differential data (+)	USB 2.0 compliant. Require differential impedance of 90 $\Omega$ .
USB_DM	10	AIO	USB differential data (-)	
USB_VBUS	8	AI	USB connection detect	Typical value: 5.0 V If unused, keep it open.
GND	3	-	Ground	

For more details about USB 2.0 specifications, visit <http://www.usb.org/home>.

The test points are recommended to be reserved for firmware upgrade and software debugging in your design. The following figure shows a reference circuit of USB interface.



*Figure 18: Reference Circuit of USB Interface*

A common mode choke L1 is recommended to be added in series between the module and your MCU to suppress EMI. Meanwhile, the 0  $\Omega$  resistors (R3 and R4) should be added in series between the module and the test points to facilitate debugging, and the resistors are not mounted by default. To ensure the integrity of USB data trace signal, L1, R3 and R4 components must be placed close to the module, and also these resistors should be placed close to each other. The extra stubs of trace must be as short as possible.

To meet USB 2.0 specification, the following principles should be complied with when design the USB interface.

- It is important to route the USB signal traces as differential pairs with ground surrounded. The impedance of USB differential trace is  $90\ \Omega$ .
- Do not route signal traces under crystals, oscillators, magnetic devices and RF signal traces. It is important to route the USB differential traces in inner-layer of the PCB, and surround the traces with ground on that layer and with ground planes above and below.
- Junction capacitance of the ESD protection component might cause influences on USB data traces, so pay attention to the selection of the component. Typically, the stray capacitance should be less than 2 pF.
- Keep the ESD protection components as close to the USB connector as possible.

### 3.12. UART Interfaces

The module provides two UART interfaces: the main UART interface and the debug UART interface. The following shows their features.

- The main UART interface supports 9600 bps, 19200 bps, 38400 bps, 57600 bps, 115200 bps, 230400 bps, 460800 bps and 921600 bps baud rates, and the default is 115200 bps. It supports RTS and CTS hardware flow control, and is used for AT command communication and data transmission.
- The debug UART interface supports 115200 bps baud rate. It is used for Linux console and log output.

The following tables show the pin definition of the two UART interfaces.

*Table 11: Pin Definition of Main UART Interface*

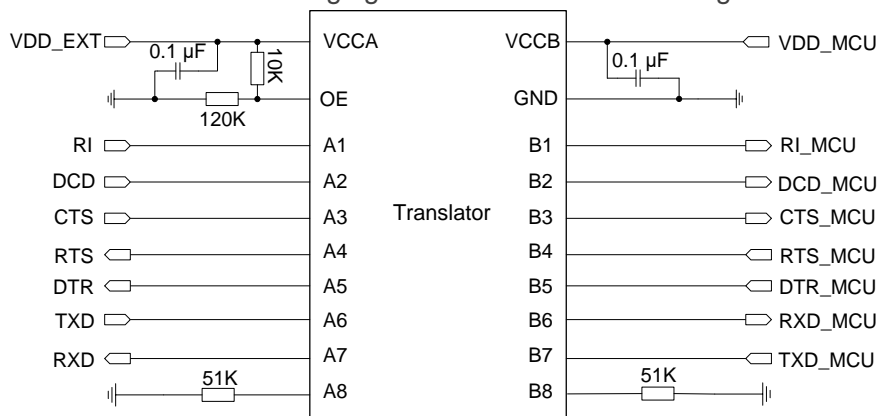
Pin Name	Pin No.	I/O	Description	Comment
RI	39	DO	Ring indication	1.8 V power domain If unused, keep them open.
DCD	38	DO	Data carrier detect	
CTS	36	DO	Clear to send signal from the module	Connect to the MCU's CTS. 1.8 V power domain If unused, keep it open.
RTS	37	DI	Request to send signal to the module	Connect to the MCU's RTS. 1.8 V power domain If unused, keep it open.
DTR	30	DI	Data terminal ready Sleep mode control	1.8 V power domain. Pulled up by default. Low level wakes up the module. If unused, keep it open.
TXD	35	DO	Transmit	1.8 V power domain. If unused, keep them open.
RXD	34	DI	Receive	

*Table 12: Pin Definition of Debug UART Interface*

Pin Name	Pin No.	I/O	Description	Comment
DBG_TXD	23	DO	Debug UART transmit	1.8 V power domain. If unused, keep them open.
DBG_RXD	22	DI	Debug UART receive	



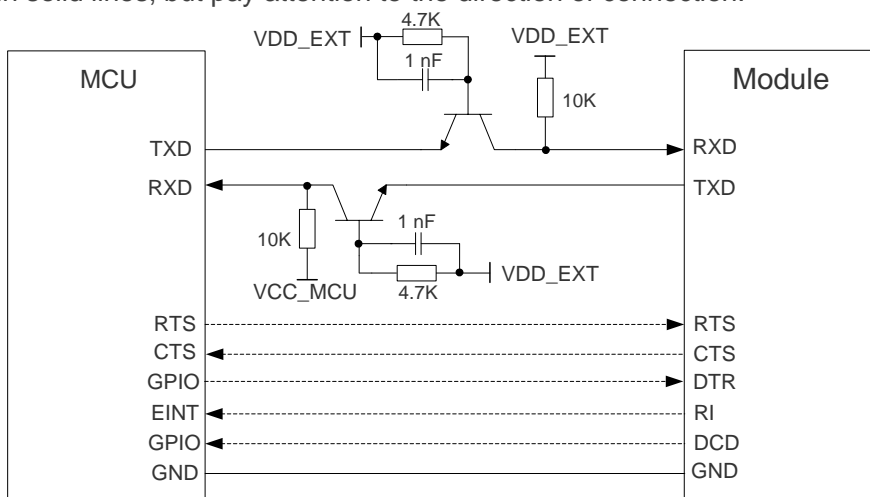
The module provides 1.8 V UART interfaces. A voltage-level translator should be used if your application is equipped with a 3.3 V UART interface. A voltage-level translator TXS0108EPWR provided by Texas Instruments is recommended. The following figure shows a reference design.



*Figure 19: Reference Circuit with Translator Chip*

Visit <http://www.ti.com> for more information.

Another example with transistor circuit is shown as below. For the design of circuits shown in dotted lines, see that shown in solid lines, but pay attention to the direction of connection.



*Figure 20: Reference Circuit with Transistor Circuit*

## NOTE

- Transistor circuit solution is not suitable for applications with high baud rates exceeding 460 kbps.
- Please note that the module's CTS is connected to the MCU's CTS, and the module's RTS is connected to the MCU's RTS.
- To increase the stability of UART communication, it is recommended to add UART hardware flow control design.

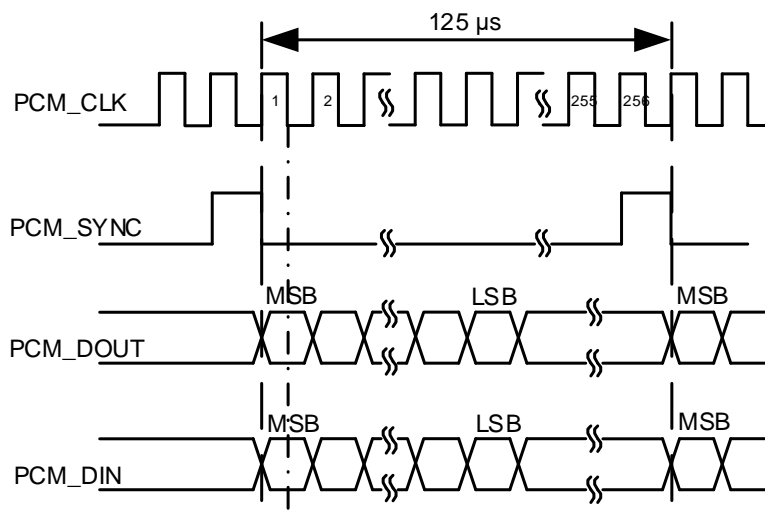
## 3.13. PCM and I2C Interfaces

The module provides one Pulse Code Modulation (PCM) digital interface for audio design which supports the following modes, and provides one I2C interface:

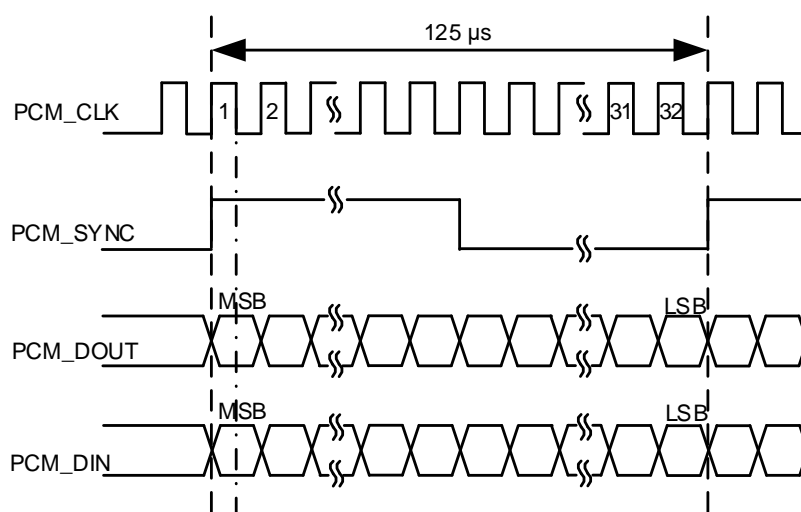
- Primary mode (short frame synchronization, works as both master and slave)
- Auxiliary mode (long frame synchronization, works as master only)

In primary mode, the data is sampled on the falling edge of the PCM\_CLK and transmitted on the rising edge. The PCM\_SYNC falling edge represents the MSB. In this mode, the PCM interface supports 256 kHz, 512 kHz, 1024 kHz or 2048 kHz PCM\_CLK at 8 kHz PCM\_SYNC, and also supports 4096 kHz PCM\_CLK at 16 kHz PCM\_SYNC.

In auxiliary mode, the data is also sampled on the falling edge of the PCM\_CLK and transmitted on the rising edge. The PCM\_SYNC rising edge represents the MSB. In this mode, the PCM interface operates with a 256 kHz, 512 kHz, 1024 kHz or 2048 kHz PCM\_CLK and an 8 kHz, 50 % duty cycle PCM\_SYNC. The module supports 16-bit linear data format. The following figures show the primary mode's timing relationship with 8 kHz PCM\_SYNC and 2048 kHz PCM\_CLK, as well as the auxiliary mode's timing relationship with 8 kHz PCM\_SYNC and 256 kHz PCM\_CLK.



*Figure 21: Primary Mode Timing*



*Figure 22: Auxiliary Mode Timing*

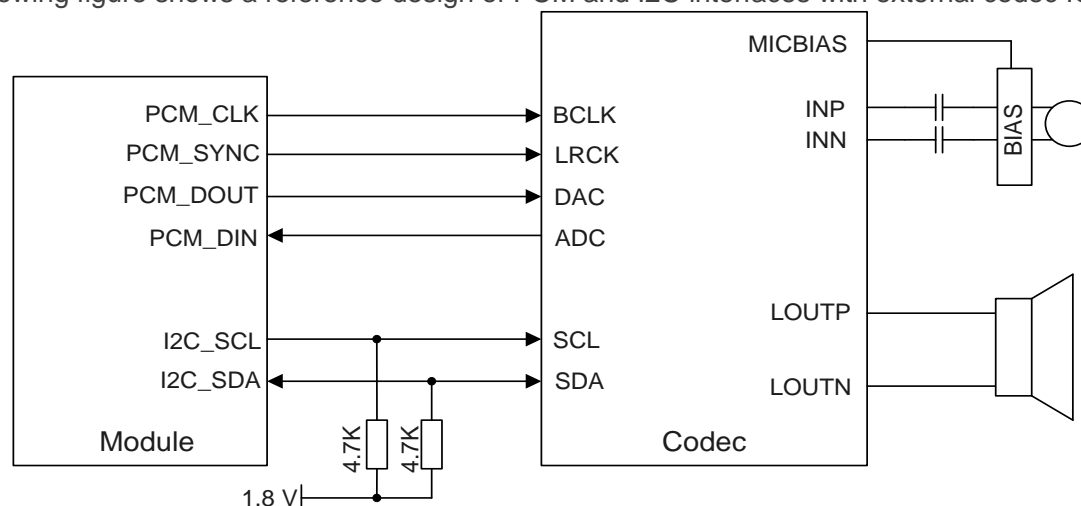
The following table shows the pin definition of PCM and I2C interfaces which can be applied on audio codec design.

*Table 13: Pin Definition of PCM and I2C Interfaces*

Pin Name	Pin No.	I/O	Description	Comment
PCM_DIN	6	DI	PCM data input	1.8 V power domain. If unused, keep them open.
PCM_DOUT	7	DO	PCM data output	
PCM_SYNC	5	DIO	PCM data frame sync	1.8 V power domain. In master mode, they are output signals. In slave mode, they are input signals. If unused, keep them open.
PCM_CLK	4	DIO	PCM data clock	
I2C_SCL	40	OD	I2C serial clock (for external codec)	Require an external pull-up to 1.8 V If unused, keep them open.
I2C_SDA	41	OD	I2C serial data (for external codec)	

The clock and mode can be configured by AT command, and the default configuration is master mode using short frame synchronization format with 2048 kHz PCM\_CLK and 8 kHz PCM\_SYNC. See **document [2]** about **AT+QDAI** for details.

The following figure shows a reference design of PCM and I2C interfaces with external codec IC.



*Figure 23: Reference Circuit of PCM Application with Audio Codec*

## NOTE

1. It is recommended to reserve an RC ( $R = 22 \Omega$ ,  $C = 22 \text{ pF}$ ) circuit on the PCM traces, especially for PCM\_CLK.
2. The module works as a master device pertaining to I2C interface.

## 3.14. SPI Interface

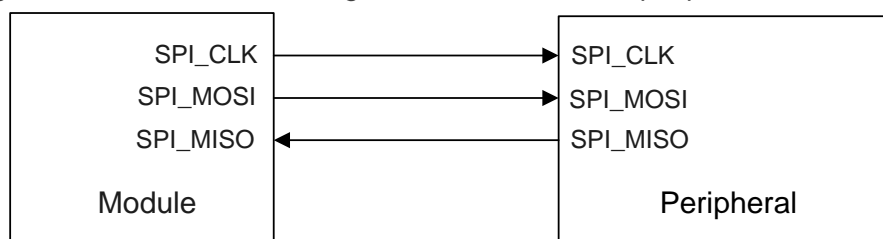
SPI interface only acts as master device. It provides a duplex, synchronous and serial communication link with the peripheral devices. It is dedicated to one-to-one connection without chip selection. Its operation voltage is 1.8 V with clock rates up to 50 MHz.

The following table shows the pin definition of SPI interface.

*Table 14: Pin Definition of SPI Interface*

Pin Name	Pin No.	I/O	Description	Comment
SPI_CLK	26	DO	SPI clock	1.8 V power domain. If unused, keep them open.
SPI_MOSI	27	DO	SPI master-out slave-in	
SPI_MISO	28	DI	SPI master-in slave-out	

The following figure shows a reference design of SPI interface with peripheral.

*Figure 24: Reference Circuit of SPI Interface with Peripheral*

## NOTE

The module provides 1.8 V SPI interface. A voltage-level translator should be used between the module and the host if your application is equipped with a 3.3 V processor or device interface.

## 3.15. Indication Signals

### 3.15.1. Network Status Indication

The module provides one network indication pin: NETLIGHT. The pin is used to indicate LED status.

The following tables describe the pin definition and logic level changes of NETLIGHT in different network status.

*Table 15: Pin Definition of Network Status Indication*

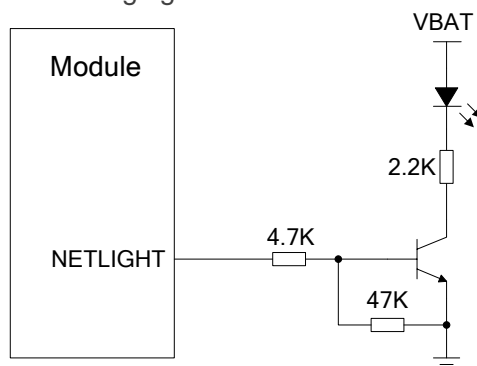
Pin Name	Pin No.	I/O	Description	Comment
NETLIGHT	21	DO	Indicate the module's network activity status	1.8 V power domain. If unused, keep it open.

*Table 16: Working State of Network Status Indication*

Pin Name	Logic Level Changes	Network Status
NETLIGHT	Blink slowly (200 ms High/1800 ms Low)	Network searching

Blink slowly (1800 ms High/200 ms Low)	Idle
Blink quickly (125 ms High/125 ms Low)	Data transmission is ongoing

A reference circuit is shown in the following figure.



*Figure 25: Reference Circuit of Network Status Indication*

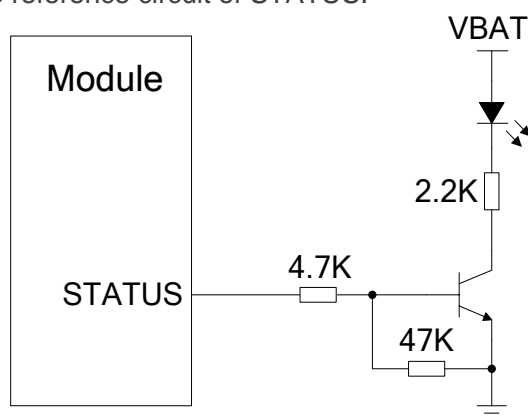
### 3.15.2. STATUS

The STATUS pin is set as the module's operation status indicator. It will output high level when the module is turned on normally. The following table describes the pin definition of STATUS.

*Table 17: Pin Definition of STATUS*

Pin Name	Pin No.	I/O	Description	Comment
STATUS	20	DO	Indicate the module's operating status	1.8 V power domain. If unused, keep it open.

The following figure shows the reference circuit of STATUS.



*Figure 26: Reference Circuit of STATUS*

### 3.15.3. RI

**AT+QCFG="risignaltpe","physical"** can be used to configure RI behaviors. See **document [3]** for details.

No matter on which port (UART port, USB AT port or USB modem port) a URC is presented, the URC will trigger the behaviors of RI pin.

## NOTE

URC can be outputted from UART port, USB AT port and USB modem port through configuration via **AT+QURCCFG**. The default port is USB AT port. See **document [2]** for details.

The default behaviors of the RI are shown as below, and can be changed by **AT+QCFG="urc/ri/ring"**. See **document [3]** for details.

*Table 18: Default Behaviors of RI*

State	Response
Idle	RI keeps at high level.
URC	RI outputs 120 ms low pulse when a new URC returns.

## 3.16. ADC Interface

The module provides one analog-to-digital converter (ADC) interface. **AT+QADC=0** can be used to read the voltage value on ADC0 pin. For more details about the command, see **document [2]**.

To improve the accuracy of ADC voltage values, the traces of ADC should be surrounded by ground.

*Table 19: Pin Definition of ADC Interface*

Pin Name	Pin No.	I/O	Description	Comment
ADC0	24	AI	General-purpose ADC interface	If unused, keep it open.

The following table describes the characteristics of ADC interface.

*Table 20: Characteristics of ADC Interface*

Parameter	Min.	Typ.	Max.	Unit
ADC0 Input Voltage Range	0.3	-	VBAT_BB	V
ADC Resolution	-	-	15	bits

## NOTE

1. It is prohibited to supply any voltage to ADC pins when ADC pin is not powered by VBAT.
2. It is recommended to use resistor divider circuit for ADC application.

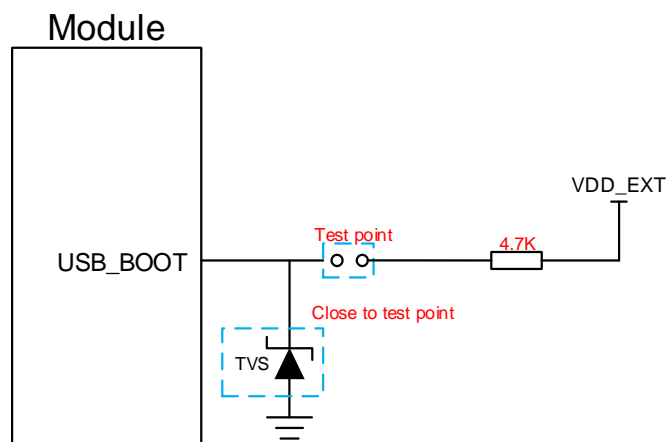
### 3.17. USB\_BOOT Interface

The module provides a USB\_BOOT pin. You can pull up USB\_BOOT to VDD\_EXT before VDD\_EXT is powered up, and the module will enter forced download mode when it is turned on. In this mode, the module supports firmware upgrade over USB interface.

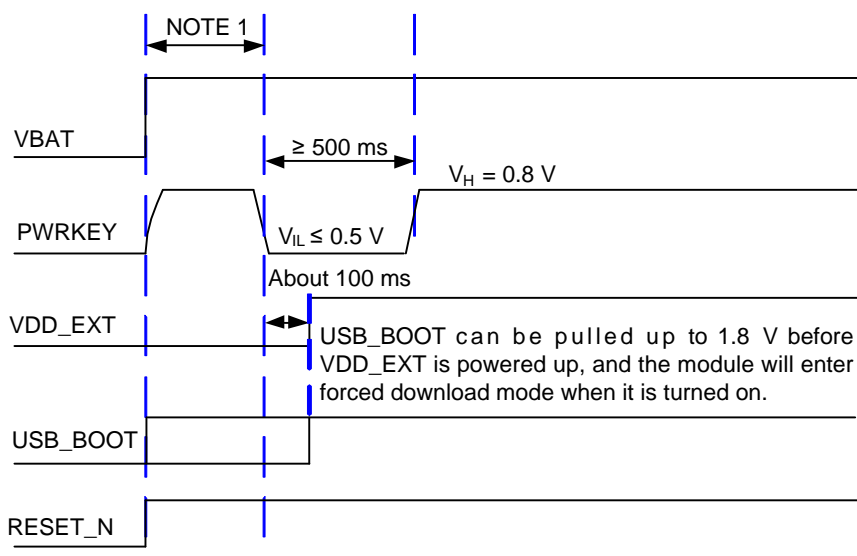
*Table 21: Pin Definition of USB\_BOOT Interface*

Pin Name	Pin No.	I/O	Description	Comment
USB_BOOT	75	DI	Force the module to enter download mode	1.8 V power domain. Active high. A test point is recommended to be reserved.

The following figures show the reference circuit of the USB\_BOOT interface and the timing sequence of entering forced download mode.



*Figure 27: Reference Circuit of USB\_BOOT Interface*



*Figure 28: Timing of Entering Forced Download Mode*

## NOTE

1. Make sure that VBAT is stable before pulling down PWRKEY pin. It is recommended that the time between powering up VBAT and pulling down PWRKEY pin is not less than 30 ms.
2. When using MCU to control the module to enter the forced download mode, follow the above timing sequence. It is not recommended to pull up USB\_BOOT to 1.8 V before powering up VBAT. Short the test points as shown in **Figure 27** can manually force the module to enter download mode.



# 4 RF Specifications

The impedance of the antenna port is 50  $\Omega$ . The antenna interfaces of the module are shown as follow:

- One main antenna interface
- One Rx-diversity antenna interface (which is used to resist the fall of signals caused by high-speed movement and multipath effect)
- One GNSS antenna interface

Appropriate antenna type and design should be used with matched antenna parameters according to specific application. It is required to perform a comprehensive functional test for the RF design before mass production of terminal products. The entire content of this chapter is provided for illustration only. Analysis, evaluation and determination are still necessary when designing target products.

## 4.1. Cellular Network

### 4.1.1. Antenna Interfaces & Frequency Bands

The pin definition of main antenna and Rx-diversity antenna interfaces is shown below.

*Table 22: Pin Definition of RF Antenna*

Pin Name	Pin No.	I/O	Description	Comment
ANT_MAIN	60	AIO	Main antenna interface	50 $\Omega$ impedance
ANT_GNSS	49	AI	GNSS antenna interface	50 $\Omega$ impedance. If unused, keep them open.
ANT_DIV	56	AI	Diversity antenna interface	

*Table 23: Module Operating Frequencies*

3GPP Band	Transmit	Receive	Unit
WCDMA B2	1850–1910	1930–1990	MHz
WCDMA B4	1710–1755	2110–2155	MHz
WCDMA B5	824–849	869–894	MHz
LTE FDD B2	1850–1910	1930–1990	MHz
LTE FDD B4	1710–1755	2110–2155	MHz
LTE FDD B5	824–849	869–894	MHz
LTE FDD B12	699–716	729–746	MHz
LTE FDD B13	777–787	746–756	MHz

LTE-FDD B25	1850–1915	1930–1995	MHz
LTE-FDD B26	814–849	859–894	MHz

#### 4.1.2. Tx Power

The following table shows the Tx power of the module.

*Table 24: Tx Power*

Frequency Band	Max. Tx Power	Min. Tx Power
WCDMA bands	23 dBm $\pm$ 2 dB	< -49 dBm
LTE-FDD bands	23 dBm $\pm$ 2 dB	< -39 dBm

#### 4.1.3. Rx Sensitivity

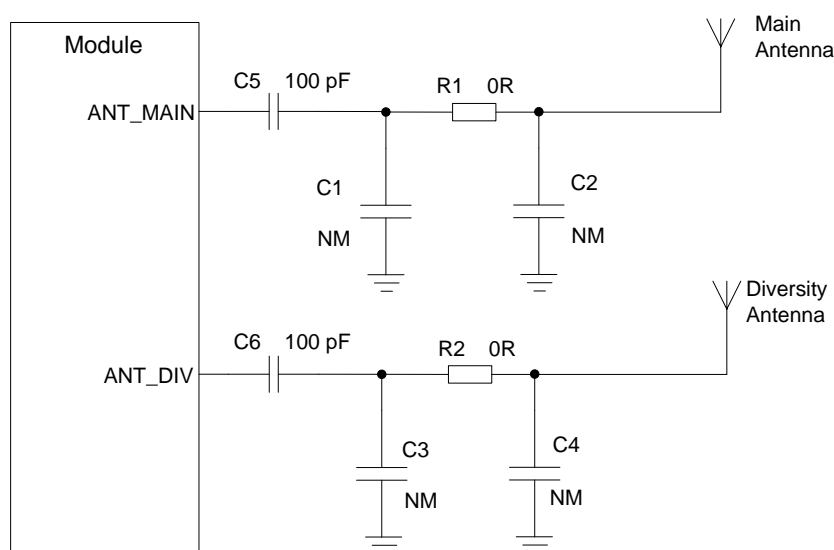
The following tables show the conducted RF receiver sensitivity of the module.

*Table 25: Conducted RF Receiver Sensitivity*

Frequency Band	Receiver Sensitivity (Typ.)			3GPP (SIMO)
	Primary	Diversity	SIMO	
WCDMA B2	-110 dBm	-110 dBm	-112.5 dBm	-104.7 dBm
WCDMA B4	-110 dBm	-110 dBm	-112.5 dBm	-106.7 dBm
WCDMA B5	-111 dBm	-111 dBm	-113 dBm	-104.7 dBm
LTE-FDD B2 (10 MHz)	-98 dBm	-99 dBm	-102.2 dBm	-94.3 dBm
LTE-FDD B4 (10 MHz)	-97.8 dBm	-99.5 dBm	-102.2 dBm	-96.3 dBm
LTE-FDD B5 (10 MHz)	-99.4 dBm	-100 dBm	-102.7 dBm	-94.3 dBm
LTE-FDD B12 (10 MHz)	-99.5 dBm	-100 dBm	-102.5 dBm	-93.3 dBm
LTE-FDD B13 (10 MHz)	-99.2 dBm	-100 dBm	-102.5 dBm	-93.3 dBm
LTE-FDD B25 (10 MHz)	-97.6 dBm	-99 dBm	-102.2 dBm	-92.8 dBm
LTE-FDD B26 (10 MHz)	-99.1 dBm	-99.9 dBm	-102.7 dBm	-93.8 dBm

#### 4.1.4. Reference Design

A reference design of ANT\_MAIN and ANT\_DIV antenna interfaces is shown as below. A dual L-type circuit should be reserved for better RF performance. The capacitors C1–C4 are not mounted by default. Place the dual L-type components (R1/C2/C1/C5 and R2/C4/C3/C6) as close to the antenna as possible.



*Figure 29: Reference Circuit of RF Antenna Interface*

## NOTE

1. Keep a proper distance between the main antenna and the Rx-diversity antenna to improve the receiver sensitivity.
2. For the operation of ANT\_MAIN and ANT\_DIV, see **AT+QCFG="divctl"** in **document [3]** for details.
3. If there is DC power at the antenna ports, C5 and C6 must be used for DC-blocking to prevent short circuit to ground. The capacitance value is recommended to be 100 pF, which can be adjusted according to actual requirements. If there is no DC power in the peripheral design, C5 and C6 should not be reserved.

## 4.2. GNSS (Optional)

The module includes a fully integrated global navigation satellite system solution that supports GPS, GLONASS, BDS, Galileo and QZSS. It supports standard NMEA 0183 protocol, and outputs NMEA sentences at 1 Hz data update rate via USB interface by default.

The GNSS engine of the module is turned off by default. It has to be turned on via AT command. For more details about GNSS engine technology and configurations, see **document [6]**.

### 4.2.1. Antenna Interfaces & Frequency Bands

The following tables show pin definition and frequency specification of GNSS antenna interface.

*Table 26: Pin Definition of GNSS Antenna Interface*

Pin Name	Pin No.	I/O	Description	Comment
----------	---------	-----	-------------	---------

ANT_GNSS	49	AI	GNSS antenna interface	50 $\Omega$ impedance. If unused, keep it open.
----------	----	----	------------------------	--

*Table 27: GNSS Frequency*

GNSS Constellation Type	Frequency	Unit
GPS	1575.42 $\pm$ 1.023	MHz
GLONASS	1597.5–1605.8	MHz
Galileo	1575.42 $\pm$ 2.046	MHz
BDS	1561.098 $\pm$ 2.046	MHz
QZSS	1575.42	MHz

#### 4.2.2. GNSS Performance

The following table shows GNSS performance of the module.

*Table 28: GNSS Performance*

Parameter	Description	Conditions	Typ.	Unit
Sensitivity	Acquisition	Autonomous	-146	dBm
	Reacquisition	Autonomous	-157	dBm
	Tracking	Autonomous	-157	dBm
TTFF	Cold start @ open sky	Autonomous	34.6	s
		XTRA start	11.57	s
	Warm start @ open sky	Autonomous	26.09	s
		XTRA start	3.7	s
	Hot start @ open sky	Autonomous	1.8	s
		XTRA start	3.4	s
Accuracy	CEP-50	Autonomous @ open sky	2.5	m

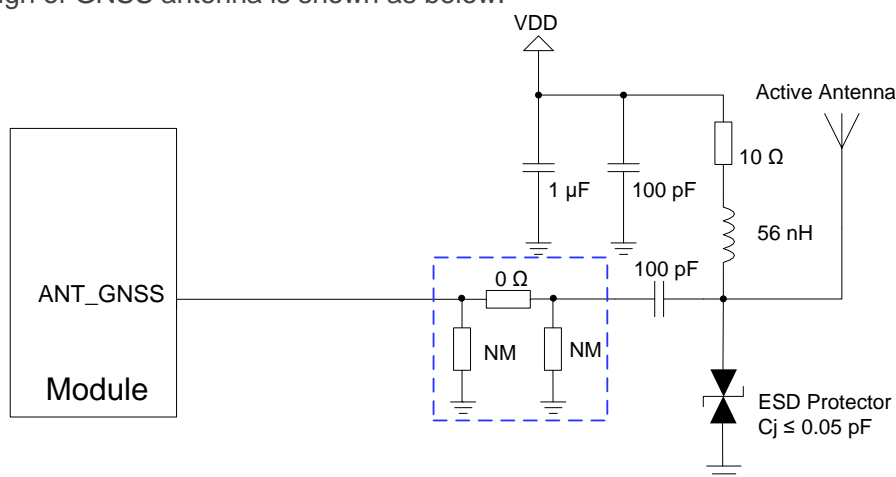
#### NOTE

1. Tracking sensitivity: the minimum GNSS signal power at which the module can maintain lock (keep positioning for at least 3 minutes continuously).
2. Reacquisition sensitivity: the minimum GNSS signal power required for the module to maintain lock within 3 minutes after loss of lock.
3. Acquisition sensitivity: the minimum GNSS signal power at which the module can fix position successfully within 3 minutes after executing cold start command.

### 4.2.3. Reference Design

In any case, it is recommended to use a passive antenna. However, if an active antenna is needed in your application, it is recommended to reserve a  $\pi$ -type attenuation circuit and use a high-performance LDO in the power system design.

A reference design of GNSS antenna is shown as below.



*Figure 30: Reference Circuit of GNSS Antenna*

### NOTE

1. An external LDO can be selected to supply power according to the active antenna requirement.
2. If the module is designed with a passive antenna, you will not need the VDD circuit.
3. It is recommended to use a passive antenna when LTE B13 is supported, as the use of active antenna may generate harmonics which will affect the GNSS performance.

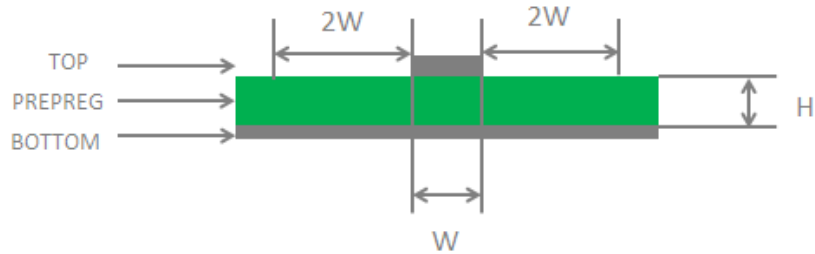
### 4.2.4. Layout Guidelines

The following layout guidelines should be taken into account in your design.

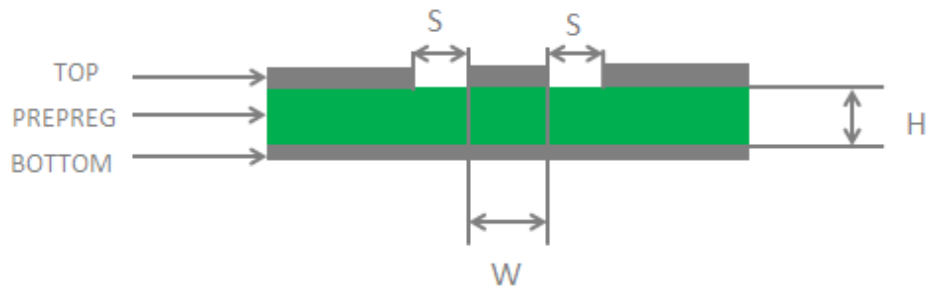
- Maximize the distance among GNSS antenna, main antenna and Rx-diversity antenna.
- Digital circuits such as (U)SIM card, USB interface, camera module and display connector should be kept away from the antennas.
- Use ground vias around the GNSS trace and sensitive analog signal traces to provide coplanar isolation and protection.
- Keep the characteristic impedance for ANT\_GNSS trace as  $50\ \Omega$ .

### 4.3. RF Routing Guidelines

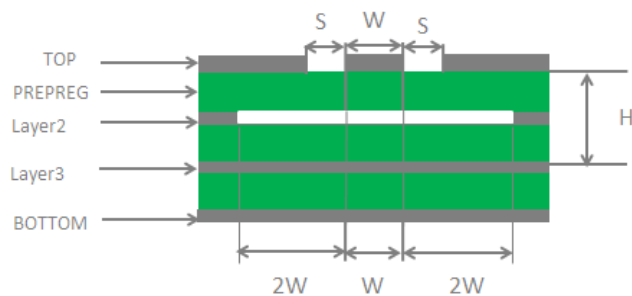
For user's PCB, the characteristic impedance of all RF traces should be controlled to  $50\ \Omega$ . The impedance of the RF traces is usually determined by the trace width ( $W$ ), the materials' dielectric constant, the height from the reference ground to the signal layer ( $H$ ), and the spacing between RF traces and grounds ( $S$ ). Microstrip or coplanar waveguide is typically used in RF layout to control characteristic impedance. The following are reference designs of microstrip or coplanar waveguide with different PCB structures.



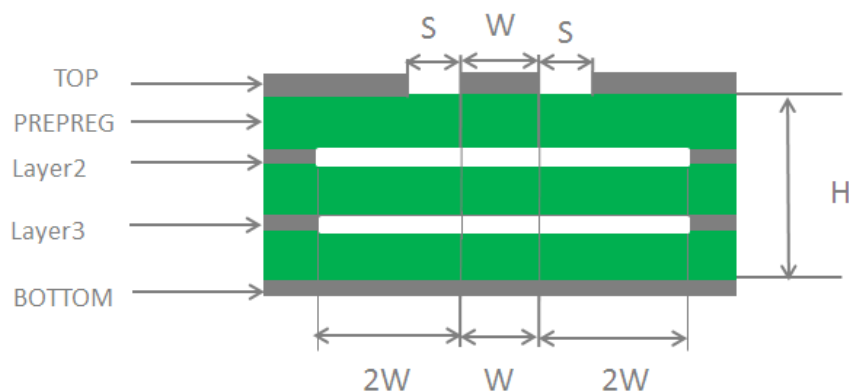
*Figure 31: Microstrip Design on a 2-layer PCB*



*Figure 32: Coplanar Waveguide Design on a 2-layer PCB*



*Figure 33: Coplanar Waveguide Design on a 4-layer PCB (Layer 3 as Reference Ground)*



*Figure 34: Coplanar Waveguide Design on a 4-layer PCB (Layer 4 as Reference Ground)*

To ensure RF performance and reliability, follow the principles below in RF layout design:

- Use an impedance simulation tool to accurately control the characteristic impedance of RF traces to  $50\ \Omega$ .
- The GND pins adjacent to RF pins should not be designed as thermal relief pads, and should be fully connected to ground.
- The distance between the RF pins and the RF connector should be as short as possible and all the right-angle traces should be changed to curved ones. The recommended trace angle is  $135^\circ$ .
- There should be clearance under the signal pin of the antenna connector or solder joint.
- The reference ground of RF traces should be complete. Meanwhile, adding some ground vias around RF traces and the reference ground could help to improve RF performance. The distance between the ground vias and RF traces should be at least twice the width of RF signal traces ( $2 \times W$ ).
- Keep RF traces away from interference sources, and avoid intersection and paralleling between traces on adjacent layers.

For more details about RF layout, refer to **document [7]**.

## 4.4. Antenna Design Requirements

The following table shows the requirements on main antenna, Rx-diversity antenna and GNSS antenna.

*Table 29: Antenna Requirements*

Type	Requirements
GNSS (Optional)	Frequency range: 1559–1609 MHz Polarization: RHCP or linear VSWR: $\leq 2$ (Typ.) Passive antenna gain: $> 0$ dBi Active antenna noise figure: $< 1.5$ dB Active antenna embedded LNA gain: $< 17$ dB
Cellular	VSWR: $\leq 2$ Efficiency: $> 30\%$ Gain: 1 dBi Max. input power: 50 W Input impedance: $50\ \Omega$ Vertical polarization Cable insertion loss: $< 1$ dB: LB ( $< 1$ GHz) $< 1.5$ dB: MB (1–2.3 GHz)

#### 4.5. RF Connector Recommendation

If RF connector is used for antenna connection, it is recommended to use U.FL-R-SMT connector provided by Hirose.

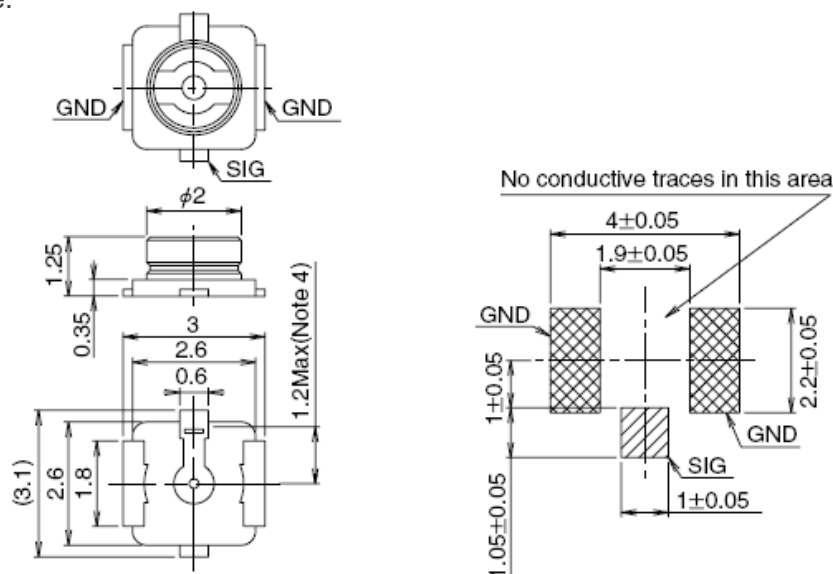
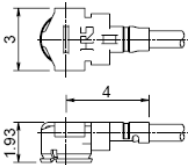
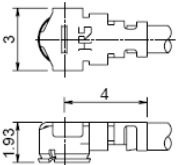
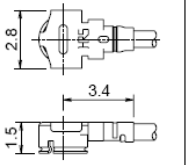
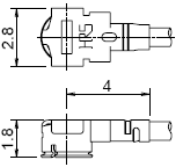
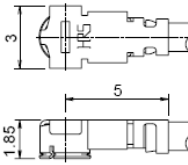


Figure 35: Dimensions of the Receptacle (Unit: mm)

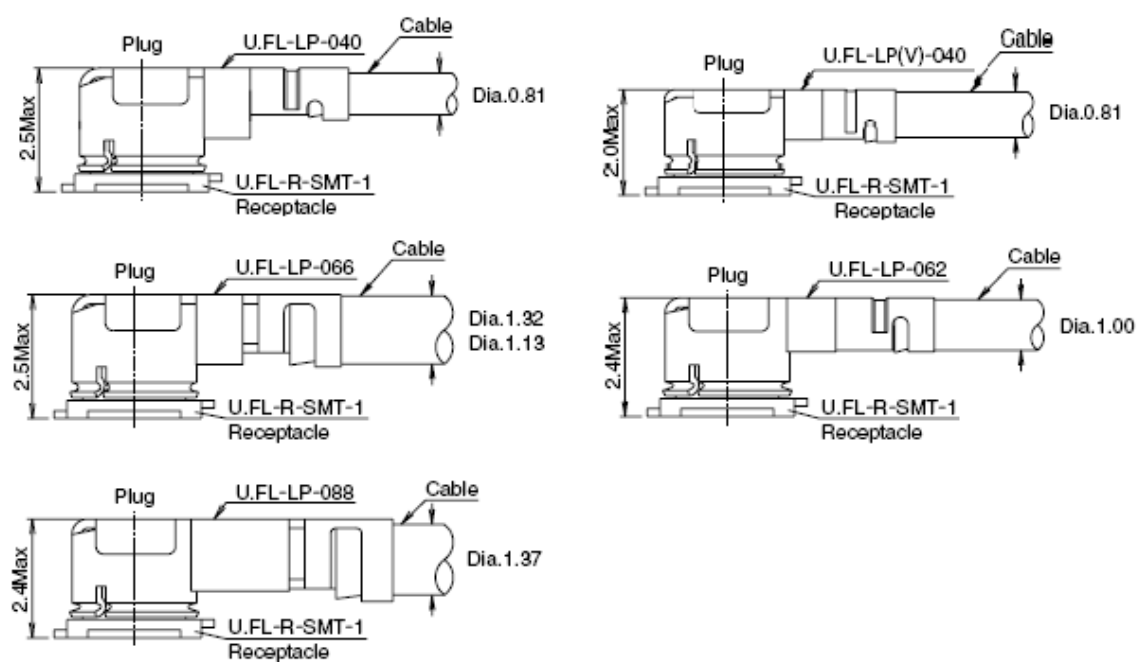
U.FL-LP series mated plugs listed in the following figure can be used to match the U.FL-R-SMT connector.

Part No.	U.FL-LP-040	U.FL-LP-066	U.FL-LP(V)-040	U.FL-LP-062	U.FL-LP-088
					
Mated Height	2.5mm Max. (2.4mm Nom.)	2.5mm Max. (2.4mm Nom.)	2.0mm Max. (1.9mm Nom.)	2.4mm Max. (2.3mm Nom.)	2.4mm Max. (2.3mm Nom.)
Applicable cable	Dia. 0.81mm Coaxial cable	Dia. 1.13mm and Dia. 1.32mm Coaxial cable	Dia. 0.81mm Coaxial cable	Dia. 1mm Coaxial cable	Dia. 1.37mm Coaxial cable
Weight (mg)	53.7	59.1	34.8	45.5	71.7
RoHS	YES				

*Figure 36: Specifications of Mated Plugs*

The following figure describes the space factor of mated connector.





*Figure 37: Space Factor of Mated Connectors (Unit: mm)*

For more details, visit <http://www.hirose.com>.

# 5 Electrical Characteristics and Reliability

## 5.1. Absolute Maximum Ratings

Absolute maximum ratings for power supply and voltage on digital and analog pins of the module are listed in the following table.

*Table 30: Absolute Maximum Ratings*

Parameter	Min.	Max.	Unit
VBAT_RF/VBAT_BB	-0.3	4.7	V
USB_VBUS	-0.3	5.5	V
Peak Current of VBAT_BB	-	0.8	A
Peak Current of VBAT_RF	-	1.3	A
Voltage at Digital Pins	-0.3	2.3	V
Voltage at ADC0	0	VBAT_BB	V

## 5.2. Power Supply Ratings

*Table 31: Power Supply Ratings*

Parameter	Description	Conditions	Min.	Typ.	Max.	Unit
VBAT	VBAT_BB and VBAT_RF	The actual input voltages must be kept between the minimum and maximum values.	3.3	3.8	4.3	V
I <sub>VBAT</sub>	Peak supply current	At maximum power control level	-	-	1.5	A
USB_VBUS	USB connection detection	-	3.0	5.0	5.25	V

## 5.3. Operating and Storage Temperatures

The operating and storage temperatures are listed in the following table.

*Table 32: Operating and Storage Temperatures*

Parameter	Min.	Typ.	Max.	Unit
Operating Temperature Range <sup>3</sup>	-35	+25	+75	°C
Extended Temperature Range <sup>4</sup>	-40	-	+85	°C
Storage Temperature Range	-40	-	+90	°C

## 5.4. Power Consumption

*Table 33: Power Consumption*

Description	Conditions	Typ.	Unit
OFF state	Power down	11	µA
	<b>AT+CFUN=0</b> (USB disconnected)	1.1	mA
	WCDMA PF = 64 (USB disconnected)	2.0	mA
	WCDMA PF = 64 (USB Suspend)	2.4	mA
Sleep state	WCDMA PF = 512 (USB disconnected)	1.5	mA
	LTE-FDD PF = 64 (USB disconnected)	2.6	mA
	LTE-FDD PF = 64 (USB Suspend)	2.8	mA
	LTE-FDD PF = 256 (USB disconnected)	1.8	mA
Idle state	WCDMA PF = 64 (USB disconnected)	18	mA
	WCDMA PF = 64 (USB connected)	35	mA
	LTE-FDD PF = 64 (USB disconnected)	18	mA
	LTE-FDD PF = 64 (USB connected)	35	mA
WCDMA data transmission	WCDMA B2 HSDPA @ 21.64 dBm	547	mA
	WCDMA B2 HSUPA @ 21.13 dBm	543	mA

<sup>3</sup> To meet the normal operating temperature range requirements, it is necessary to ensure effective thermal dissipation, e.g., by adding passive or active heatsinks, heat pipes, vapor chambers. Within this range, the module's indicators comply with 3GPP specification requirements.

<sup>4</sup> To meet the extended operating temperature range requirements, it is necessary to ensure effective thermal dissipation, e.g., by adding passive or active heatsinks, heat pipes, vapor chambers. Within this range, the module remains the ability to establish and maintain functions such as SMS and data transmission, without any unrecoverable malfunction. Radio spectrum and radio network remain uninfluenced, whereas the value of one or more parameters, such as Pout, may decrease and fall below the range of the 3GPP specified tolerances. When the temperature returns to the normal operating temperature range, the module's indicators will comply with 3GPP specification requirements again.

LTE data transmission	WCDMA B4 HSDPA @ 22.15 dBm	554	mA
	WCDMA B4 HSUPA @ 22.21 dBm	541	mA
	WCDMA B5 HSDPA @ 22.39 dBm	502	mA
	WCDMA B5 HSUPA @ 22.12 dBm	509	mA
	LTE-FDD B2 @ 23.07 dBm	691	mA
	LTE-FDD B4 @ 23.09 dBm	713	mA
	LTE-FDD B5 @ 23.31 dBm	580	mA
	LTE-FDD B12 @ 23.30 dBm	627	mA
	LTE-FDD B13 @ 23.32 dBm	619	mA
	LTE-FDD B25 @ 23.03 dBm	693	mA
	LTE-FDD B26 @ 22.97 dBm	628	mA

## 5.5. GNSS Power Consumption

*Table 34: GNSS Power Consumption*

Description	Conditions	Typ.	Unit
Acquisition ( <b>AT+CFUN=0</b> )	Cold start @ Passive antenna	54	mA
	Hot start @ Passive antenna	54	mA
	Lost state @ Passive antenna	53	mA
Tracking ( <b>AT+CFUN=0</b> )	Open sky @ Passive antenna	32	mA

## 5.6. ESD Protection

Static electricity occurs naturally and it may damage the module. Therefore, applying proper ESD countermeasures and handling methods is imperative. For example, wear anti-static gloves during the development, production, assembly and testing of the module; add ESD protection components to the ESD sensitive interfaces and points in the product design.

*Table 35: Electrostatic Discharge Characteristics (Temperature: 25–30 °C, Humidity: 40 ±5 %)*

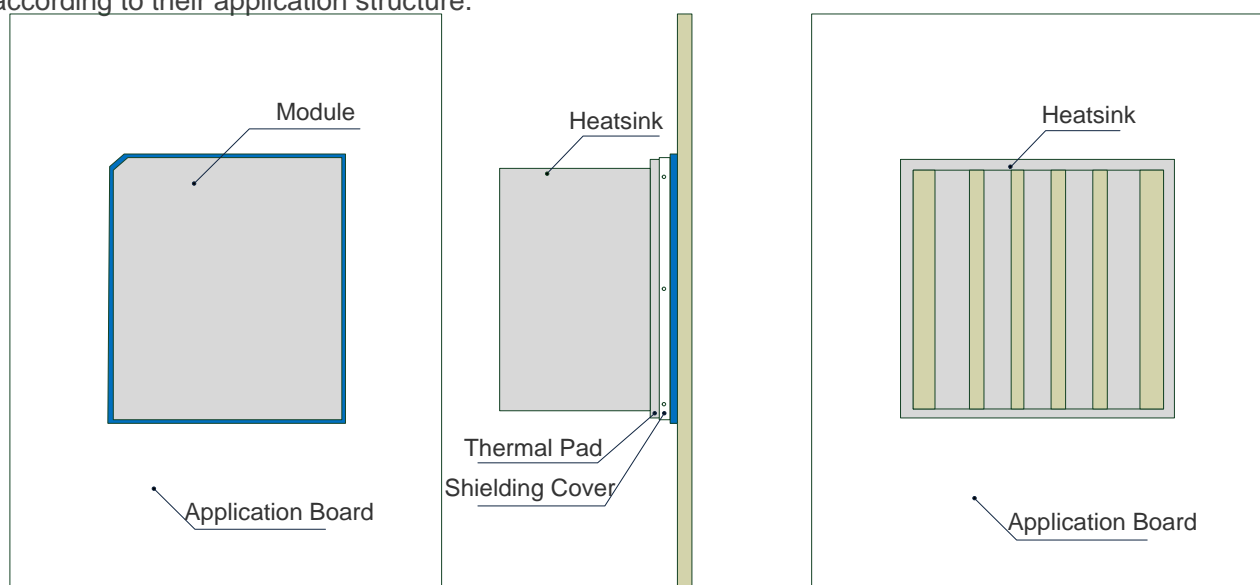
Tested Interfaces	Contact Discharge	Air Discharge	Unit
VBAT, GND	±5	±10	kV
All Antenna Interfaces	±4	±8	kV
Other Interfaces	±0.5	±1	kV

## 5.7. Thermal Dissipation

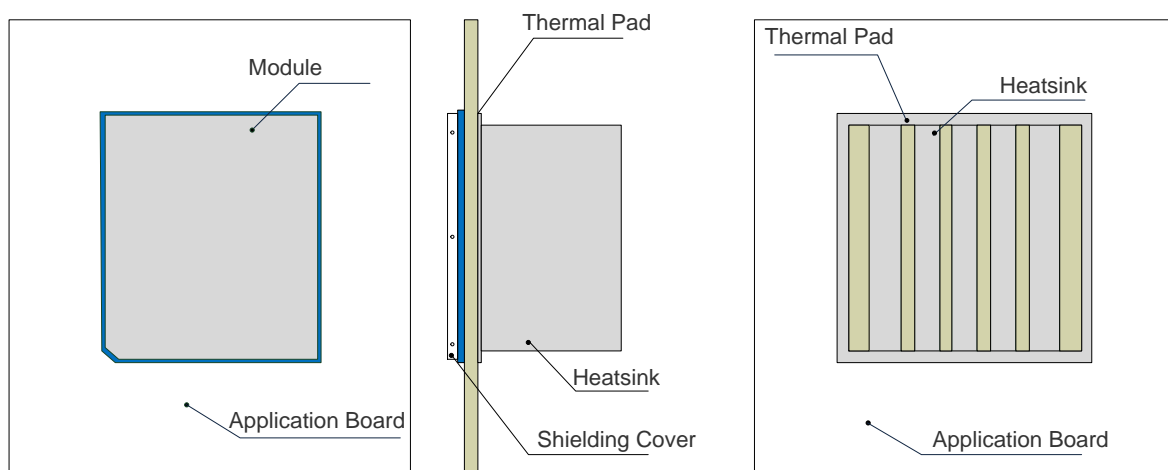
In order to achieve better performance of the module, it is recommended to comply with the following principles for thermal consideration:

- On your PCB design, please keep placement of the module away from heating sources, especially high power components such as ARM processor, audio power amplifier and power supply.
- Do not place components on the opposite side of the PCB area where the module is mounted, in order to facilitate adding of heatsink when necessary.
- Do not apply solder mask on the opposite side of the PCB area where the module is mounted, so as to ensure better heat dissipation performance.
- The reference ground of the area where the module is mounted should be complete, and add ground vias as many as possible for better heat dissipation.
- Make sure the ground pads of the module and PCB are fully connected.
- According to your application demands, the heatsink can be mounted on the top of the module, or the opposite side of the PCB area where the module is mounted, or both of them.
- The heatsink should be designed with as many fins as possible to increase heat dissipation area. Meanwhile, a thermal pad with high thermal conductivity should be used between the heatsink and module/PCB.

The following shows two kinds of heatsink designs for reference and you can choose one or both of them according to their application structure.



*Figure 38: Referenced Heatsink Design (Heatsink at the Top of the Module)*



*Figure 39: Referenced Heatsink Design (Heatsink at the Backside of Customers' PCB)*

## NOTE

The module offers the best performance when the internal BB chip stays below 105 °C. When the maximum temperature of the BB chip reaches or exceeds 105 °C, the module works normal but provides reduced performance (such as RF output power and data rate). When the maximum BB chip temperature reaches or exceeds 115 °C, the module will disconnect from the network, and it will recover to network connected state after the maximum temperature falls below 115 °C. Therefore, the thermal design should be maximally optimized to make sure the maximum BB chip temperature always maintains below 105 °C. You can execute **AT+QTEMP** and get the maximum BB chip temperature from the first returned value. For more details, see **document [8]**.

# 6 Mechanical Information

This chapter describes the mechanical dimensions of the module. All dimensions are measured in millimeter (mm), and the dimensional tolerances are  $\pm 0.2$  mm unless otherwise specified.

## 6.1. Mechanical Dimensions

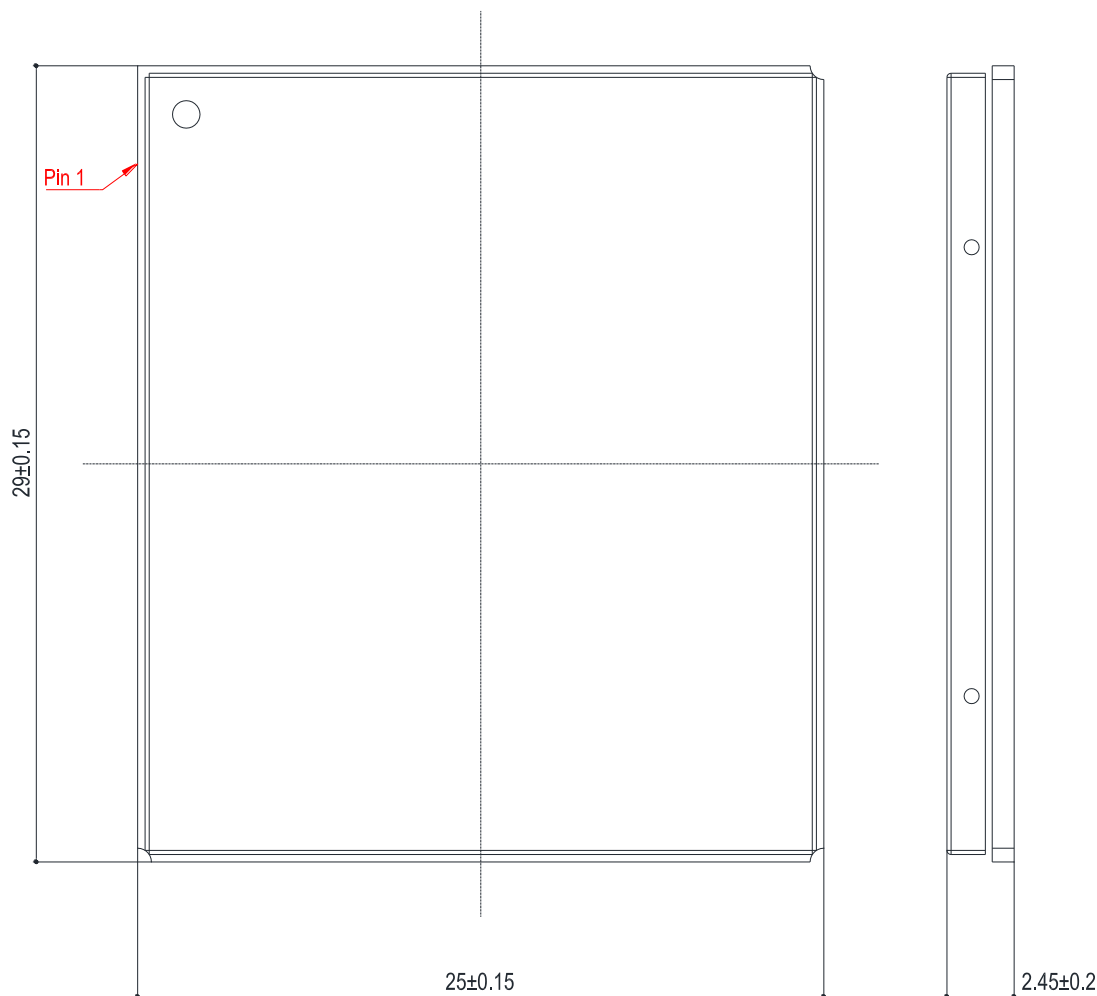


Figure 40: Top and Side Dimensions

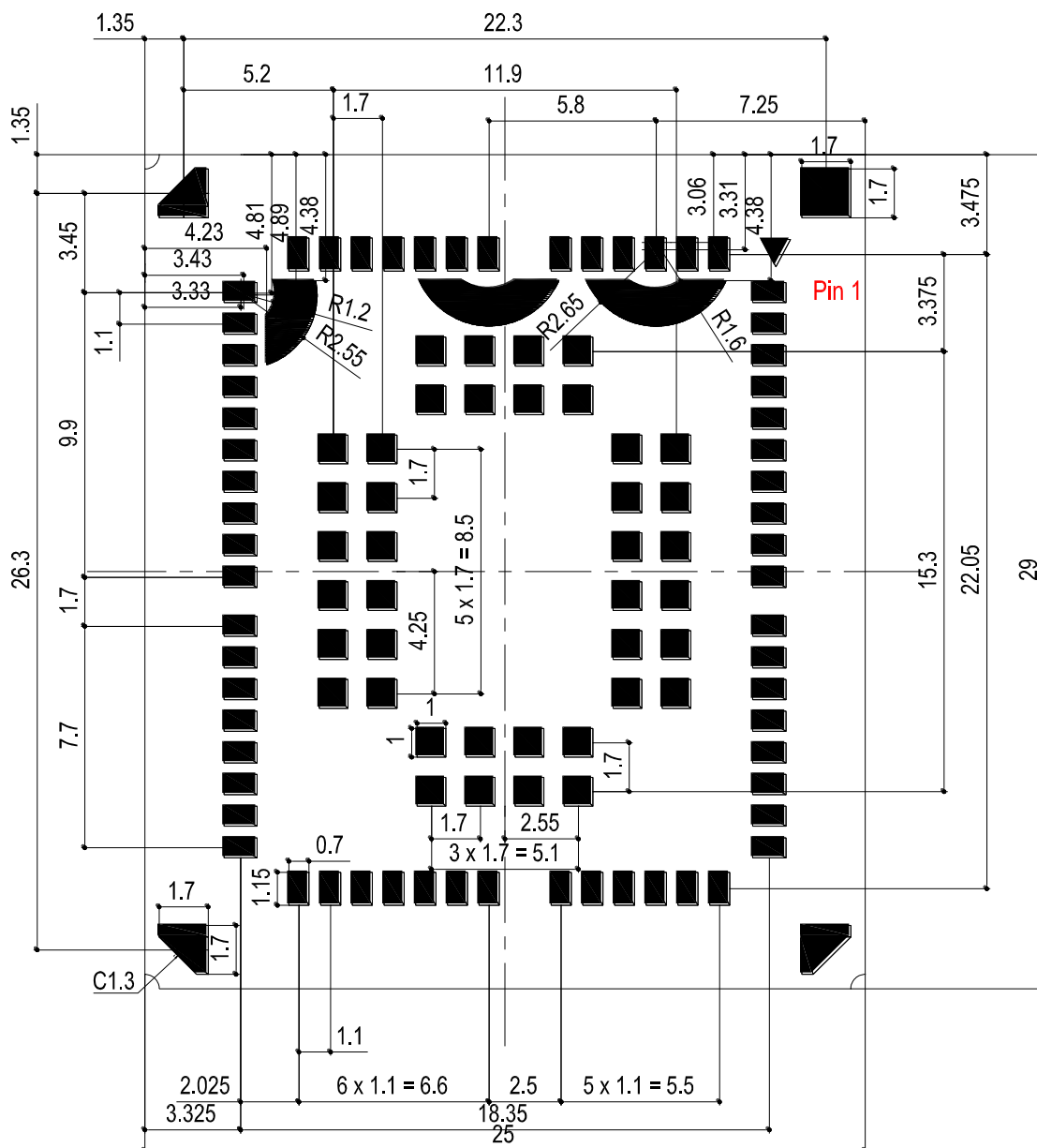


Figure 41: Bottom Dimensions (Top View)

## NOTE

The package warpage level of the module refers to JEITA ED-7306 standard.

## 6.2. Recommended Footprint



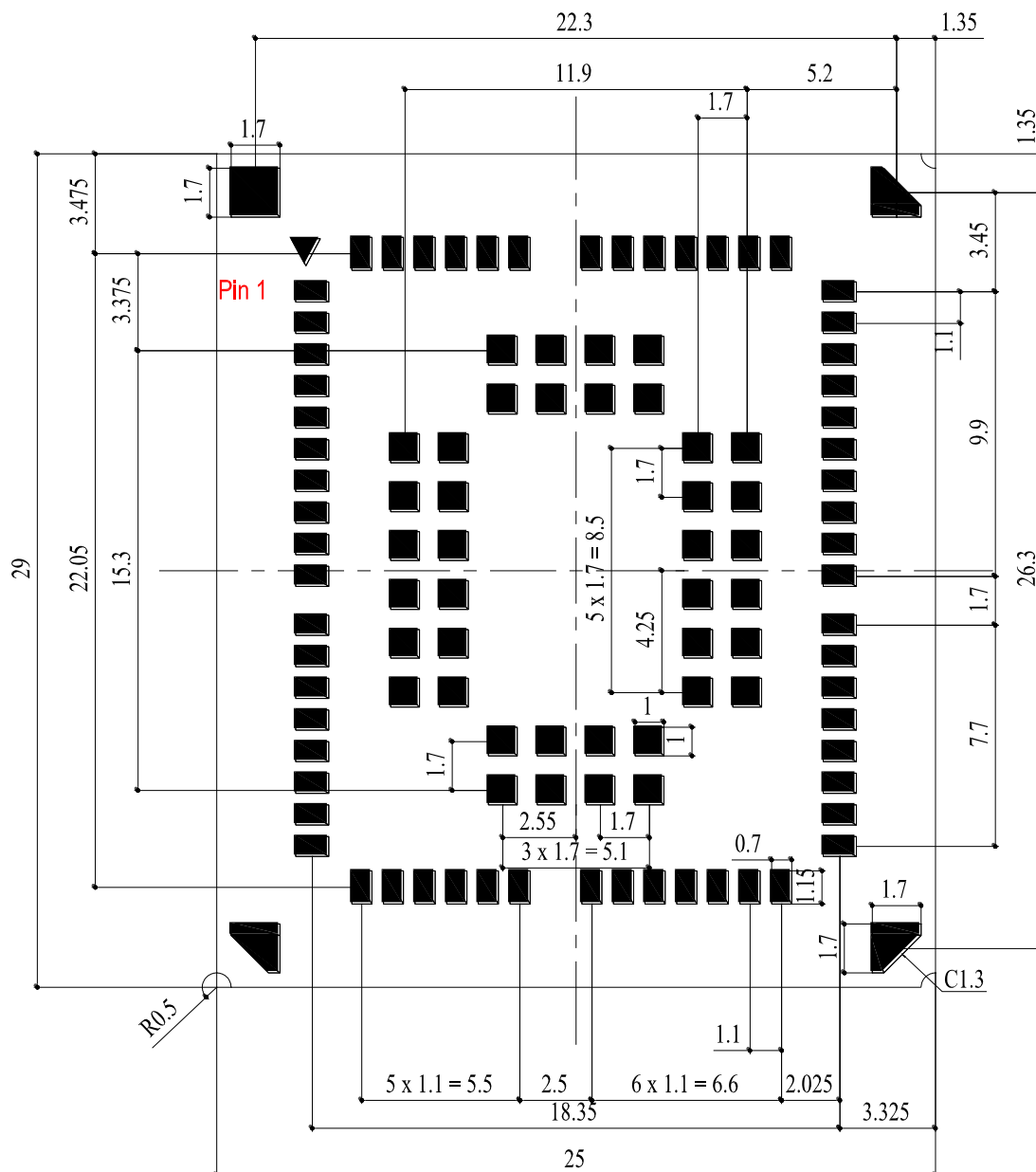


Figure 42: Recommended Footprint

## NOTE

Keep at least 3 mm between the module and other components on the motherboard to improve soldering quality and maintenance convenience.

### 6.3. Top and Bottom Views

*Figure 43: Top and Bottom Views of the Module*

## NOTE

Images above are for illustration purpose only and may differ from the actual module. For authentic appearance and label, please refer to the module received from NetPrisma.

# 7 Storage, Manufacturing and Packaging

## 7.1. Storage Conditions

The module is provided with vacuum-sealed packaging. MSL of the module is rated as 3. The storage requirements are shown below.

1. Recommended Storage Condition: the temperature should be  $23 \pm 5$  °C and the relative humidity should be 35–60 %.
2. Shelf life (in a vacuum-sealed packaging): 12 months in Recommended Storage Condition.
3. Floor life: 168 hours <sup>5</sup> in a factory where the temperature is  $23 \pm 5$  °C and relative humidity is below 60 %. After the vacuum-sealed packaging is removed, the module must be processed in reflow soldering or other high-temperature operations within 168 hours. Otherwise, the module should be stored in an environment where the relative humidity is less than 10 % (e.g., a dry cabinet).
4. The module should be pre-baked to avoid blistering, cracks and inner-layer separation in PCB under the following circumstances:
  - The module is not stored in Recommended Storage Condition;
  - Violation of the third requirement mentioned above;
  - Vacuum-sealed packaging is broken, or the packaging has been removed for over 24 hours;
  - Before module repairing.
5. If needed, the pre-baking should follow the requirements below:
  - The module should be baked for 8 hours at  $120 \pm 5$  °C;
  - The module must be soldered to PCB within 24 hours after the baking, otherwise it should be put in a dry environment such as in a dry cabinet.

### NOTE

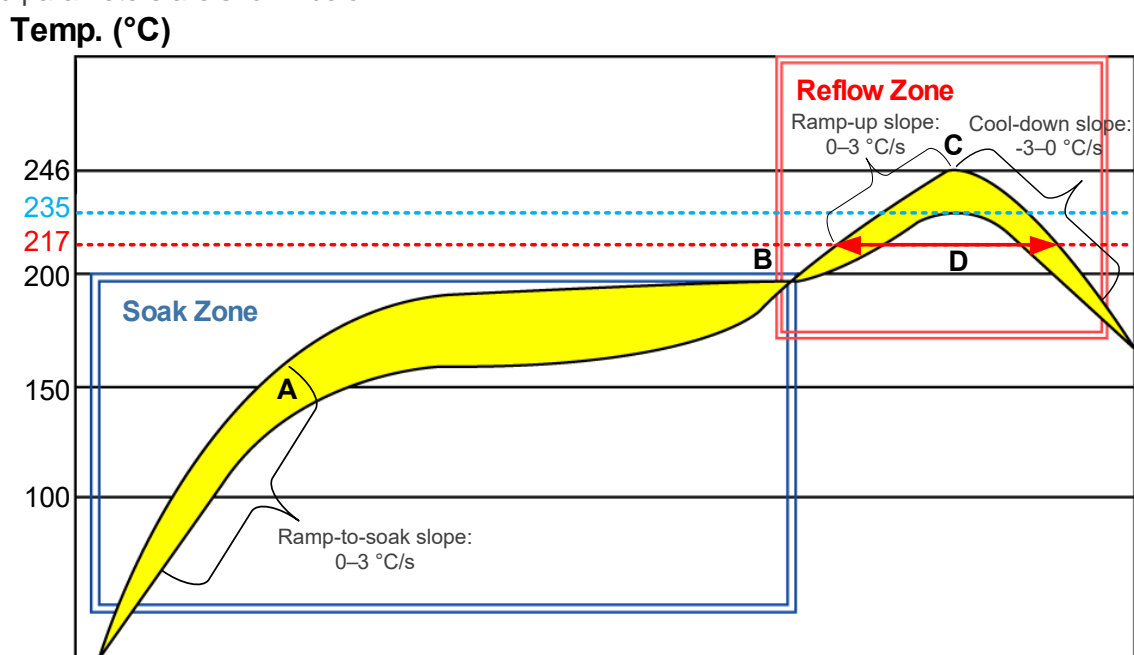
1. To avoid blistering, layer separation and other soldering issues, extended exposure of the module to the air is forbidden.
2. Take out the module from the package and put it on high-temperature-resistant fixtures before baking. If shorter baking time is desired, see *IPC/JEDEC J-STD-033* for the baking procedure.
3. Pay attention to ESD protection, such as wearing anti-static gloves, when touching the modules.

## 7.2. Manufacturing and Soldering

Push the squeegee to apply the solder paste on the surface of stencil, thus making the paste fill the stencil openings and then penetrate to the PCB. Apply proper force on the squeegee to produce a clean stencil surface on a single pass. To guarantee module soldering quality, the thickness of stencil for the module is recommended to be 0.13–0.18 mm. For more details, see **document [9]**.

<sup>5</sup> This floor life is only applicable when the environment conforms to *IPC/JEDEC J-STD-033*. It is recommended to start the solder reflow process within 24 hours after the package is removed if the temperature and moisture do not conform to, or are not sure to conform to *IPC/JEDEC J-STD-033*. And do not unpack the modules in large quantities until they are ready for soldering.

The recommended peak reflow temperature should be 235–246 °C, with 246 °C as the absolute maximum reflow temperature. To avoid damage to the module caused by repeated heating, it is recommended that the module should be mounted only after reflow soldering for the other side of PCB has been completed. The recommended reflow soldering thermal profile (lead-free reflow soldering) and related parameters are shown below.



*Figure 44: Recommended Reflow Soldering Thermal Profile*

*Table 36: Recommended Thermal Profile Parameters*

Factor	Recommended Value
<b>Soak Zone</b>	
Ramp-to-soak slope	0–3 °C/s
Soak time (between A and B: 150 °C and 200 °C)	70–120 s
<b>Reflow Zone</b>	
Ramp-up slope	0–3 °C/s
Reflow time (D: over 217°C)	40–70 s
Max. temperature	235–246 °C
Cool-down slope	-3–0 °C/s
<b>Reflow Cycle</b>	
Max. reflow cycle	1

## NOTE

1. The above profile parameter requirements are for the measured temperature of the solder joints. Both the hottest and coldest spots of solder joints on the PCB should meet the above requirements.
2. If a conformal coating is necessary for the module, do NOT use any coating material that may chemically react with the PCB or shielding cover, and prevent the coating material from flowing into the module.
3. Avoid using ultrasonic technology for module cleaning since it can damage crystals inside the module.
4. Avoid using materials that contain mercury (Hg), such as adhesives, for module processing, even if the materials are RoHS compliant and their mercury content is below 1000 ppm (0.1 %).
5. Due to the complexity of the SMT process, please contact NetPrisma Technical Support in advance for any situation that you are not sure about, or any process (e.g. selective soldering, ultrasonic soldering) that is not mentioned in **document [10]**.

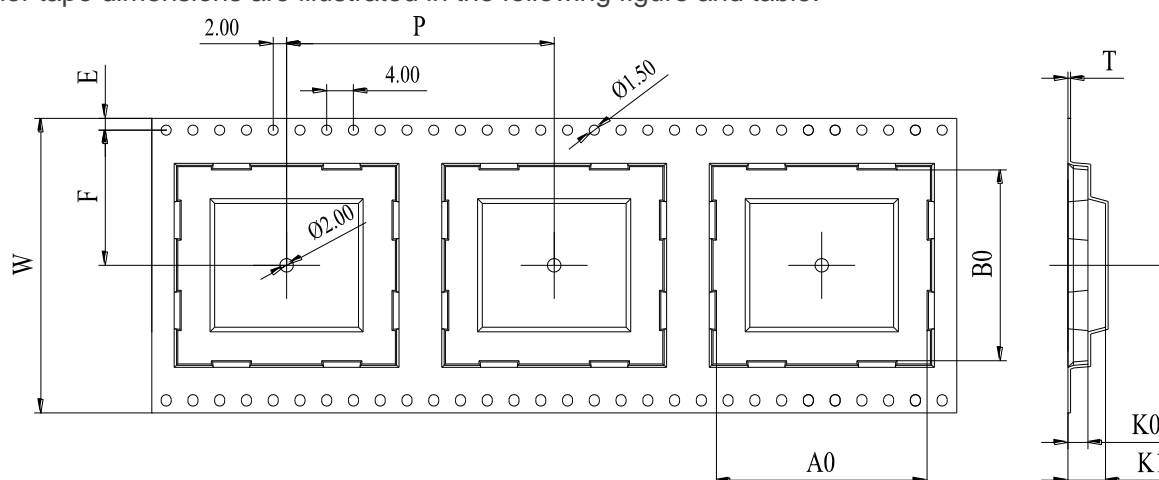
### 7.3. Packaging Specification

This chapter outlines the key packaging parameters and processes. All figures below are for reference purposes only, as the actual appearance and structure of packaging materials may vary in delivery.

The modules are packed in a tape and reel packaging as specified in the sub-chapters below.

#### 7.3.1. Carrier Tape

Carrier tape dimensions are illustrated in the following figure and table.



*Figure 45: Carrier Tape Dimension Drawing (Unit: mm)*

*Table 37: Carrier Tape Dimension Table (Unit: mm)*

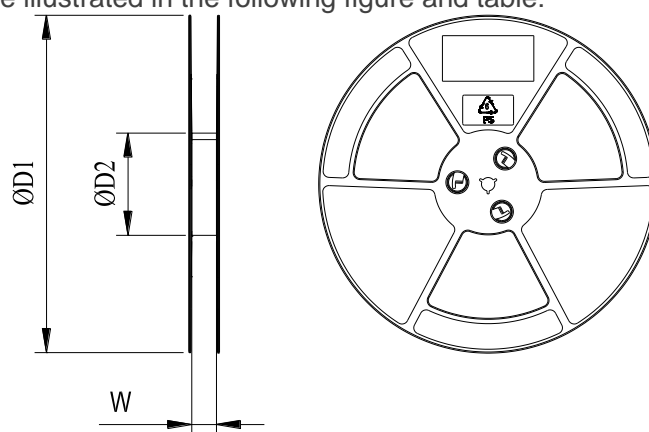
W	P	T	A0	B0	K0	K1	F	E
44	32	0.35	25.5	29.5	3.2	5.8	20.2	1.75

**NOTE**

Actual pads in kind prevail when mounting.

**7.3.2. Plastic Reel**

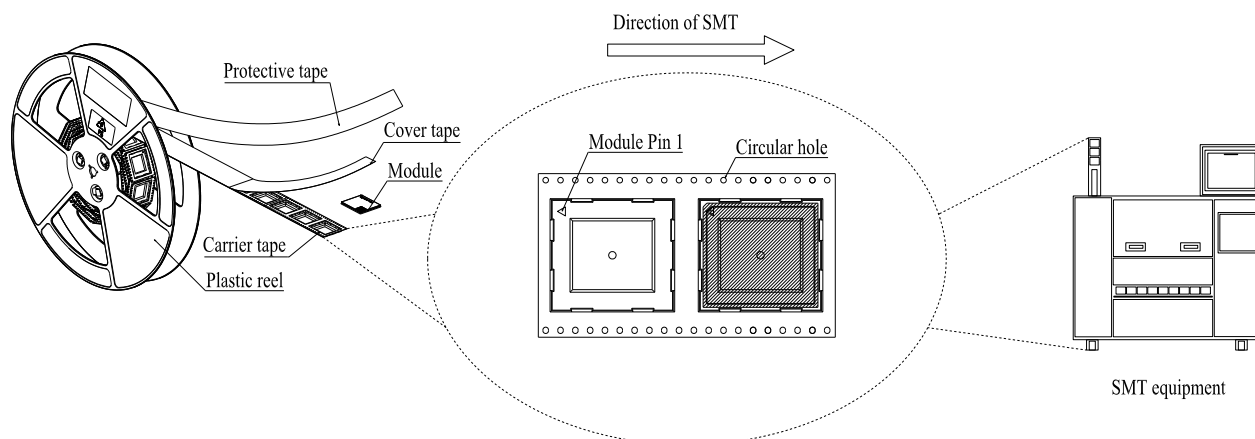
Plastic reel dimensions are illustrated in the following figure and table:



*Figure 46: Plastic Reel Dimension Drawing*

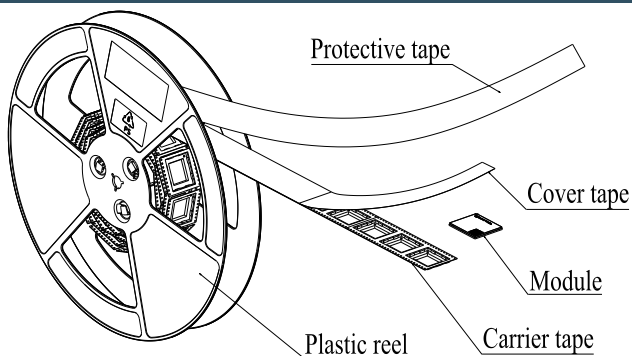
*Table 38: Plastic Reel Dimension Table (Unit: mm)*

ØD1	ØD2	W
330	100	44.5

**7.3.3. Mounting Direction**

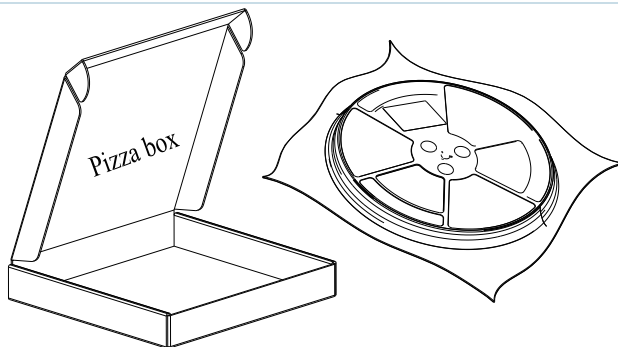
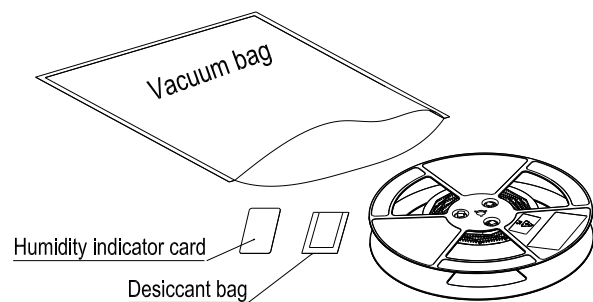
*Figure 47: Mounting Direction*

### 7.3.4. Packaging Process



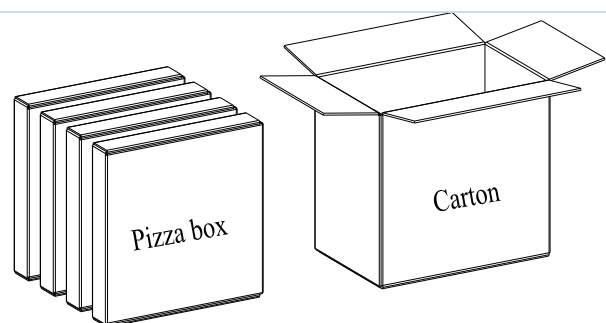
Place the modules onto the carrier tape cavity and cover them securely with cover tape. Wind the heat-sealed carrier tape onto a plastic reel and apply a protective tape for additional protection. 1 plastic reel can load 250 modules.

Place the packaged plastic reel, humidity indicator card and desiccant bag into a vacuum bag, and vacuumize it.



Place the vacuum-packed plastic reel into a pizza box.

Place the 4 packaged pizza boxes into 1 carton and seal it. 1 carton can pack 1000 modules.



*Figure 48: Packaging Process*

# 8 Appendix References

*Table 39: Related Documents*

Document Name
[1] NetPrisma_UMTS&LTE_EVB_User_Guide
[2] NetPrisma_LUH23-LD_AT_Commands_Manual
[3] NetPrisma_LUH23-LD_QCFG_AT_Commands_Manual
[4] NetPrisma_LUH23-LD_Low_Power_Mode_Application_Note
[5] NetPrisma_LUH23-LD_AT+QDSIM_Command_Manual
[6] NetPrisma_LUH23-LD_GNSS_Application_Note
[7] NetPrisma_RF_Layout_Application_Note
[8] NetPrisma_LUH23-LD_Software_Thermal_Management_Guide
[9] NetPrisma_Module_Stencil_Design_Requirements
[10] NetPrisma_Module_SMT_Application_Note

*Table 40: Terms and Abbreviations*

Abbreviation	Description
3GPP	3rd Generation Partnership Project
ADC	Analog-to-Digital Converter
AMR	Adaptive Multi-rate
BDS	BeiDou Navigation Satellite System
bps	Bits Per Second
CHAP	Challenge Handshake Authentication Protocol
C <sub>j</sub>	Junction Capacitance
CMUX	Connection Multiplexing
CS	Coding Scheme
CTS	Clear To Send



DC-HSDPA	Dual-carrier High Speed Downlink Packet Access
DC-HSPA+	Dual-carrier High Speed Packet Access
DCS	Data Coding Scheme
DDR	Double Data Rate
DFOTA	Delta Firmware Upgrade Over-The-Air
DL	Downlink
DRX	Discontinuous Reception
DTR	Data Terminal Ready
DTX	Discontinuous Transmission
ESD	Electrostatic Discharge
EVB	Evaluation Board
FDD	Frequency Division Duplex
FILE	File Protocol
FTP	File Transfer Protocol
FTPS	FTP over SSL
GLONASS	GLObalnaya NAVigatsionnaya Sputnikovaya Sistema, the Russian Global Navigation Satellite System
GNSS	Global Navigation Satellite System
GPS	Global Positioning System
HSDPA	High Speed Downlink Packet Access
HSPA	High Speed Packet Access
HSUPA	High Speed Uplink Packet Access
HTTP	Hypertext Transfer Protocol
HTTPS	Hypertext Transfer Protocol Secure
I/O	Input/Output
Inom	Nominal Current
LED	Light Emitting Diode
LGA	Land Grid Array
LNA	Low Noise Amplifier

LTE	Long Term Evolution
M2M	Machine to Machine
MCS	Modulation and Coding Scheme
MCU	Microcontroller Unit
ME	Mobile Equipment
MIMO	Multiple Input Multiple Output
MMS	Multimedia Messaging Service
MO	Mobile Originated
MQTT	Message Queuing Telemetry Transport
MS	Mobile Station (GSM engine)
MSL	Moisture Sensitivity Level
MT	Mobile Terminated
NAND	Non-volatile Memory Device
NITZ	Network Identity and Time Zone
NMEA	NMEA (National Marine Electronics Association) 0183 Interface Standard
NTP	Network Time Protocol
PA	Power Amplifier
PAP	Password Authentication Protocol
PCB	Printed Circuit Board
PCM	Pulse Code Modulation
PDU	Protocol Data Unit
PING	Packet Internet Groper
PMIC	Power Management IC
PPP	Point-to-Point Protocol
QAM	Quadrature Amplitude Modulation
QPSK	Quadrature Phase Shift Keying
QZSS	Quasi-Zenith Satellite System
RF	Radio Frequency

RHCP	Right Hand Circularly Polarized
RoHS	Restriction of Hazardous Substances
RTS	Request to Send
Rx	Receive
SAW	Surface Acoustic Wave
SMD	Surface Mount Device
SMTP	Simple Mail Transfer Protocol
SMTPS	Simple Mail Transfer Protocol Secure
SMS	Short Message Service
SPI	Serial Peripheral Interface
SSL	Secure Sockets Layer
TCP	Transmission Control Protocol
Tx	Transmit
UART	Universal Asynchronous Receiver/Transmitter.
UDP	User Datagram Protocol
UL	Uplink
UMTS	Universal Mobile Telecommunications System
URC	Unsolicited Result Code
(U)SIM	(Universal) Subscriber Identity Module
USB	Universal Serial Bus
V <sub>max</sub>	Maximum Voltage
V <sub>nom</sub>	Nominal Voltage
V <sub>min</sub>	Minimum Voltage
V <sub>IHmax</sub>	Maximum High-level Input Voltage
V <sub>IHmin</sub>	Minimum High-level Input Voltage
V <sub>ILmax</sub>	Maximum Low-level Input Voltage
V <sub>ILmin</sub>	Minimum Low-level Input Voltage
V <sub>I</sub> max	Absolute Maximum Input Voltage

$V_{Imin}$	Absolute Minimum Input Voltage
$V_{OHmin}$	Minimum High-level Output Voltage
$V_{OLmax}$	Maximum Low-level Output Voltage
$V_{OLmin}$	Minimum Low-level Output Voltage
VSWR	Voltage Standing Wave Ratio
WCDMA	Wideband Code Division Multiple Access

## Document History

Revision	Date	Changes
A	2025-01-23	The first revision.

# FCC Statement

**FCC ID: 2BEY3LUH23LDA**

## OEM/Integrators Installation Manual

### Important Notice to OEM integrators

1. This module is limited to OEM installation ONLY.
2. This module is limited to installation in mobile or fixed applications, according to Part 2.1091(b).
3. The separate approval is required for all other operating configurations, including portable configurations with respect to Part 2.1093 and different antenna configurations
4. For FCC Part 15.31 (h) and (k): The host manufacturer is responsible for additional testing to verify compliance as a composite system. When testing the host device for compliance with Part 15 Subpart B, the host manufacturer is required to show compliance with Part 15 Subpart B while the transmitter module(s) are installed and operating. The modules should be transmitting and the evaluation should confirm that the module's intentional emissions are compliant (i.e. fundamental and out of band emissions). The host manufacturer must verify that there are no additional unintentional emissions other than what is permitted in Part 15 Subpart B or emissions are complaint with the transmitter(s) rule(s). The Grantee will provide guidance to the host manufacturer for Part 15 B requirements if needed.

### Important Note

notice that any deviation(s) from the defined parameters of the antenna trace, as described by the instructions, require that the host product manufacturer must notify to NetPrisma that they wish to change the antenna trace design. In this case, a Class II permissive change application is required to be filed by the USI, or the host manufacturer can take responsibility through the change in FCC ID (new application) procedure followed by a Class II permissive change application.

### End Product Labeling

When the module is installed in the host device, the FCC/IC ID label must be visible through a window on the final device or it must be visible when an access panel, door or cover is easily re-moved. If not, a second label must be placed on the outside of the final device that contains the following text:

"Contains FCC ID: 2BEY3LUH23LDA"

"Contains IC: 32052-LUH23LDA"

The FCC ID/IC ID can be used only when all FCC/IC compliance requirements are met.

### Antenna Installation

- (1) The antenna must be installed such that 20 cm is maintained between the antenna and users,
- (2) The transmitter module may not be co-located with any other transmitter or antenna.

In the event that these conditions cannot be met (for example certain laptop configurations or co-location with another transmitter), then the FCC/IC authorization is no longer considered valid and the FCC ID/IC ID cannot be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate FCC/IC authorization.

Antenna Type	Max Gain	
External Antenna	LTE Band 2: 1.59dBi	WCDMA Band 2: 1.59dBi WCDMA Band 4: 2.0dBi WCDMA Band 5: 2.13dBi
	LTE Band 4: 2.0dBi	
	LTE Band 5: 2.13dBi	
	LTE Band 12: 3.26dBi	
	LTE Band 13: 4.45dBi	
	LTE Band 25: 1.59dBi	
	LTE Band 26: 2.53dBi	

### Manual Information to the End User

The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module in the user's manual of the end product which integrates this module. The end user manual shall include all required regulatory information/warning as show in this manual.

### Federal Communication Commission Interference Statement

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate this equipment. This transmitter must not be co-located or operating in conjunction with any other antenna or transmitter.

### List of applicable FCC rules

This module has been tested and found to comply with part 15, part 22, part 24, part 27 and part 90 requirements for Modular Approval.

The modular transmitter is only FCC authorized for the specific rule parts (i.e., FCC transmitter rules) listed on the grant, and that the host product manufacturer is responsible for compliance to any other FCC rules that apply to the host not covered by the modular transmitter grant of certification. If the grantee markets their product as being Part 15 Subpart B compliant (when it also contains unintentional-radiator digital circuitry), then the grantee shall provide a notice stating that the final host product still requires Part 15 Subpart B compliance testing with the modular transmitter installed.

### This device is intended only for OEM integrators under the following conditions: (For module device use)

- 1) The antenna must be installed such that 20 cm is maintained between the antenna and users, and
- 2) The transmitter module may not be co-located with any other transmitter or antenna.

As long as 2 conditions above are met, further transmitter test will not be required. However, the OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this module installed.

### Radiation Exposure Statement

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20 cm between the radiator & your body.

## IC Statement

### IC: 32052-LUH23LDA

### Industry Canada Statement

This device complies with Industry Canada's licence-exempt RSSs. Operation is subject to the following two conditions:

- (1) This device may not cause interference; and
- (2) This device must accept any interference, including interference that may cause undesired operation of the device.

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes:

- (1) l'appareil ne doit pas produire de brouillage, et
- (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement."

### Radiation Exposure Statement

This equipment complies with IC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20 cm between the radiator & your body.

### **Déclaration d'exposition aux radiations:**

Cet équipement est conforme aux limites d'exposition aux rayonnements ISED établies pour un environnement non contrôlé. Cet équipement doit être installé et utilisé avec un minimum de 20 cm de distance entre la source de rayonnement et votre corps.

### **This device is intended only for OEM integrators under the following conditions: (For module device use)**

- 1) The antenna must be installed such that 20 cm is maintained between the antenna and users, and
- 2) The transmitter module may not be co-located with any other transmitter or antenna.

As long as 2 conditions above are met, further transmitter test will not be required. However, the OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this module installed.

### **Cet appareil est conçu uniquement pour les intégrateurs OEM dans les conditions suivantes: (Pour utilisation de dispositif module)**

- 1) L'antenne doit être installée de telle sorte qu'une distance de 20 cm est respectée entre l'antenne et les utilisateurs, et
- 2) Le module émetteur peut ne pas être coïmplanté avec un autre émetteur ou antenne.

Tant que les 2 conditions ci-dessus sont remplies, des essais supplémentaires sur l'émetteur ne seront pas nécessaires. Toutefois, l'intégrateur OEM est toujours responsable des essais sur son produit final pour toutes exigences de conformité supplémentaires requis pour ce module installé.

### **IMPORTANT NOTE:**

In the event that these conditions cannot be met (for example certain laptop configurations or colocation with another transmitter), then the Canada authorization is no longer considered valid and the IC ID cannot be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate Canada authorization.

### **NOTE IMPORTANTE:**

Dans le cas où ces conditions ne peuvent être satisfaites (par exemple pour certaines configurations d'ordinateur portable ou de certaines co-localisation avec un autre émetteur), l'autorisation du Canada n'est plus considéré comme valide et l'ID IC ne peut pas être utilisé sur le produit final. Dans ces circonstances, l'intégrateur OEM sera chargé de réévaluer le produit final (y compris l'émetteur) et l'obtention d'une autorisation distincte au Canada.

### **End Product Labeling**

This transmitter module is authorized only for use in device where the antenna may be installed such that 20 cm may be maintained between the antenna and users. The final end product must be labeled in a visible area with the following: "Contains IC: 32052-LUH23LDA".

### **Plaque signalétique du produit final**

Ce module émetteur est autorisé uniquement pour une utilisation dans un dispositif où l'antenne peut être installée de telle sorte qu'une distance de 20cm peut être maintenue entre l'antenne et les utilisateurs. Le produit final doit être étiqueté dans un endroit visible avec l'inscription suivante: "Contient des IC: 32052-LUH23LDA".

### **Manual Information To the End User**

The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module in the user's manual of the end product which integrates this module. The end user manual shall include all required regulatory information/warning as show in this manual.

### **Manuel d'information à l'utilisateur final**

L'intégrateur OEM doit être conscient de ne pas fournir des informations à l'utilisateur final quant à la façon d'installer ou de supprimer ce module RF dans le manuel de l'utilisateur du produit final qui intègre ce module.

Le manuel de l'utilisateur final doit inclure toutes les informations réglementaires requises et avertissements comme indiqué dans ce manuel.